



# MPP Project Review 2006 - HLL

## Outline

DEPFET (ILC)

Sub electron noise measurements - RNDR

Back illuminated SiPM (MAGIC, EUSO)

Detectors for SLHC  
and XFEL



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der Max-Planck-  
Institute  
für Physik und  
extraterrestrische  
Physik

## HLL - Mitarbeiter

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<sup>c</sup> PN Sensor

WHI:

6 physicists and engineers

4 technicians

2 secretaries

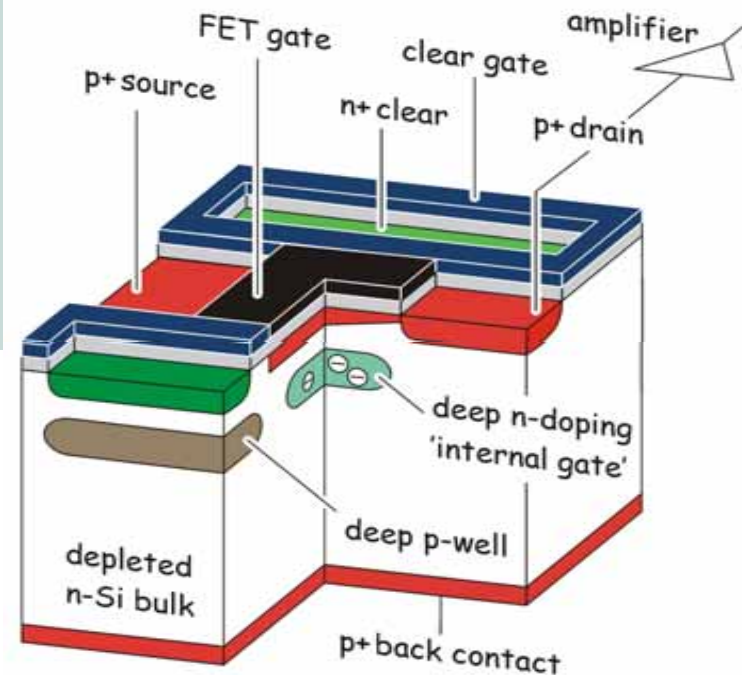
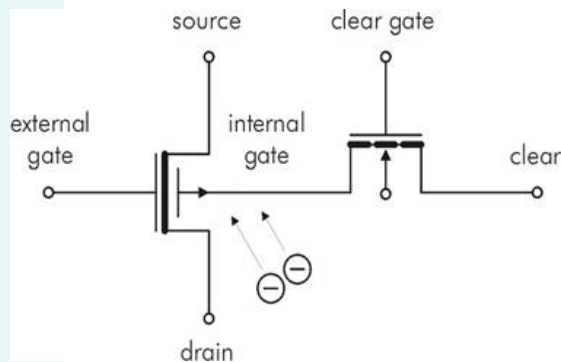
3 PhD students

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## DEPFET Principle of Operation

- A p-FET transistor is integrated in each pixel
- A potential minimum for electrons is created under the channel by sideward depletion
- Electrons are collected in the "internal gate" and modulate the transistor current
- Signal charge is removed via a clear contact

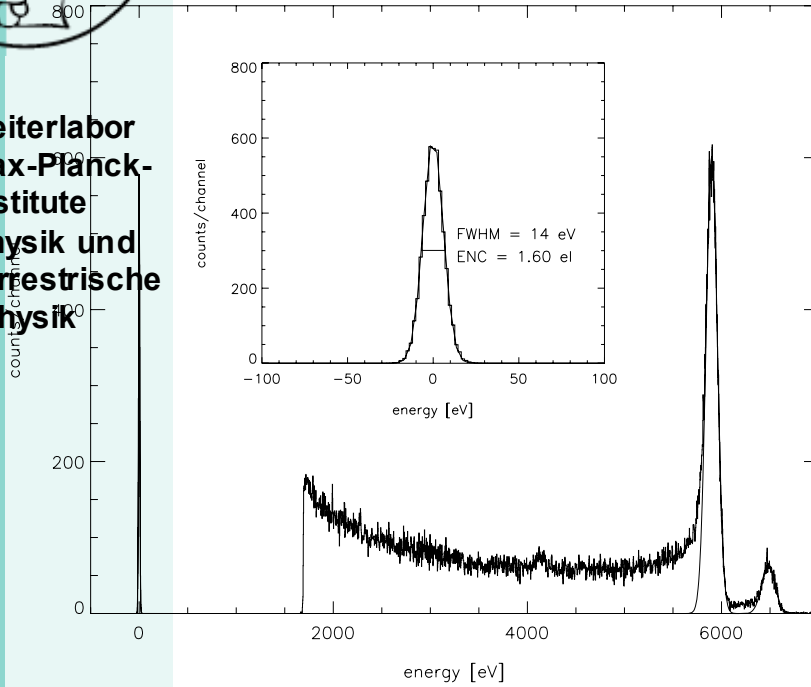


- Fast signal collection in fully depleted bulk
- Low noise due to small capacitance and internal amplification
- Transistor can be switched off by external gate – charge collection is then still active!



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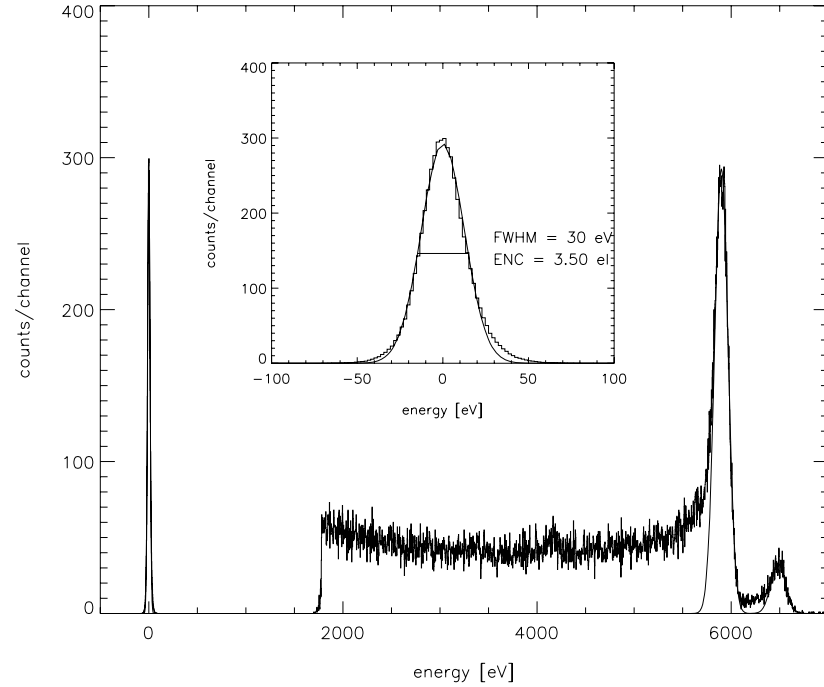
## DEPFET for ILC - $^{55}\text{Fe}$ Spectrum (single ILC pixel)



**non-irradiated**  
 $V_{\text{thresh}} \approx -0.2\text{V}$ ,  $V_{\text{gate}} = -2\text{V}$   
 $I_{\text{drain}} = 41 \mu\text{A}$   
time cont. shaping  $\tau = 10 \mu\text{s}$

Noise ENC = 1.6 e<sup>-</sup> (rms)

at  $T > 23 \text{ degC}$



**912 krad  $^{60}\text{Co}$**   
 $V_{\text{thresh}} \approx -4.0\text{V}$ ,  $V_{\text{gate}} = -6.0\text{V}$   
 $I_{\text{drain}} = 40 \mu\text{A}$   
time cont. shaping  $\tau = 10 \mu\text{s}$

Noise ENC = 3.5 e<sup>-</sup> (rms)

at  $T > 23 \text{ degC}$



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# DEPFETs at ILC speed

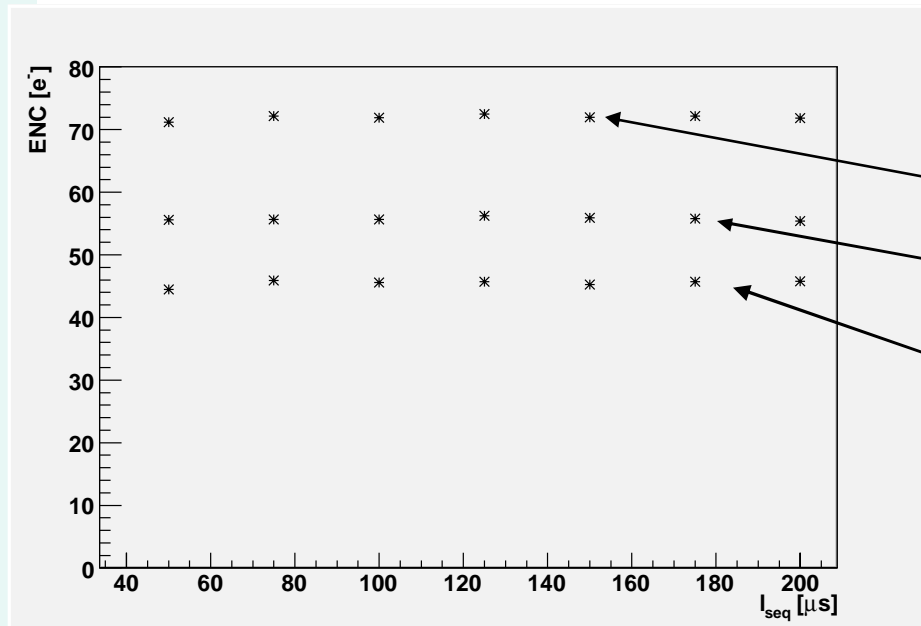
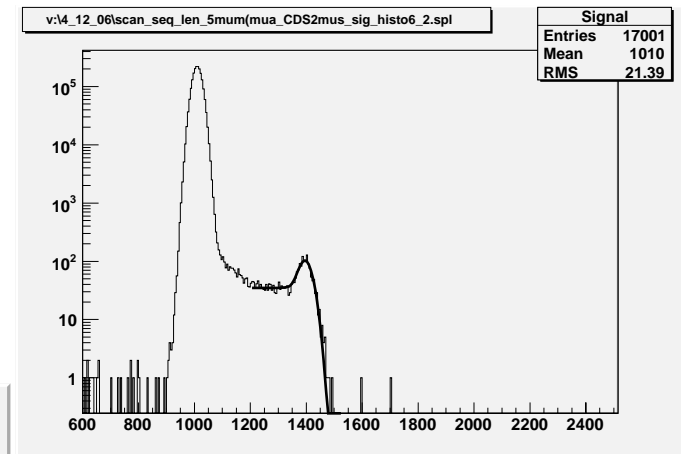
Single DePMOS devices

LG = 5 $\mu$ m

fast transimpedance amplifier

BW = 55MHz

## Fe<sup>55</sup> spectrum



DEPFET + Amplifier

Amplifier

DEPFET only

Goal for ILC about ENC ca.100e-

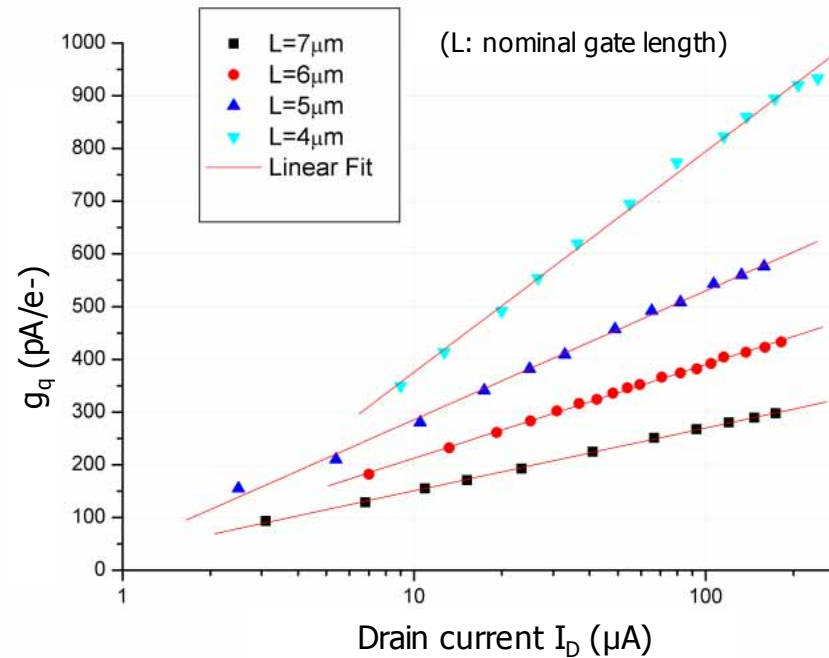
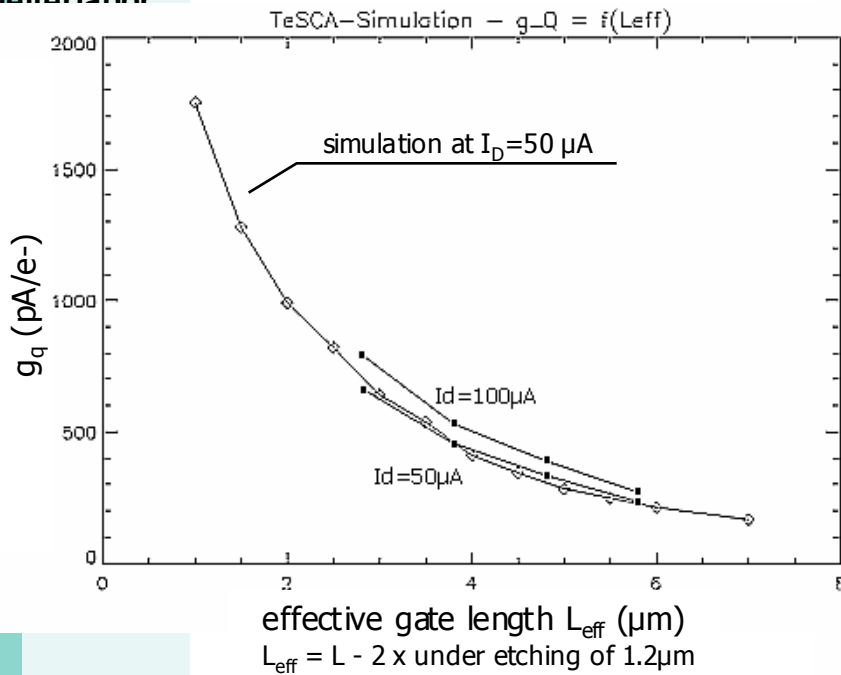
integration time (μs)



# Internal amplification $g_q$

$$g_q = \frac{dI_D}{dQ} = -\frac{\mu_p}{L^2} (V_{GS} - V_{th}) \quad (\text{neglecting short channel effects})$$

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 der MPI für Extrakt



» As long as noise is dominated by r/o chip  $\rightarrow$  S/N linear with  $g_q$

» PXD4 has L=6µm, some matrices in PXD5 have now L=4µm  $\rightarrow$  expect factor 2 better S/N

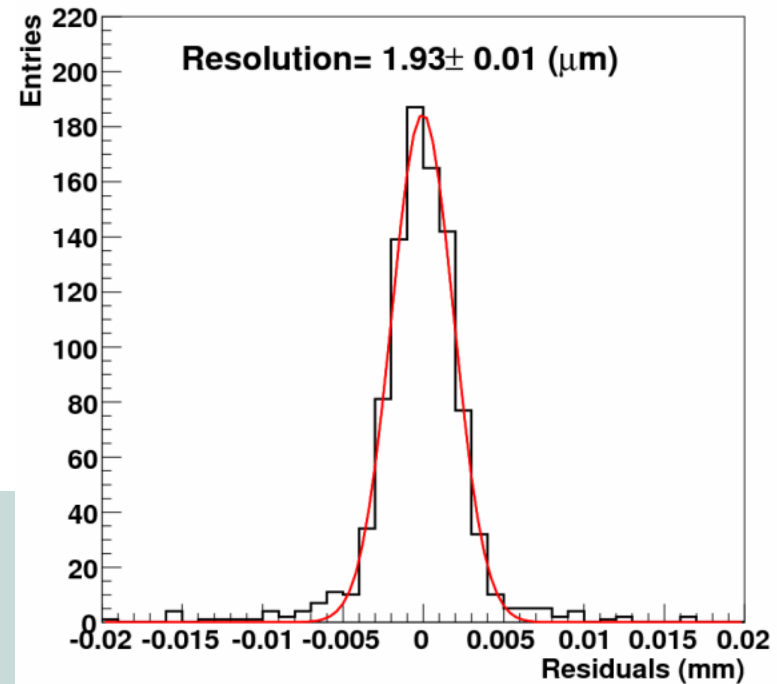


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## Testbeam at CERN - Position resolution

For  $5\sigma$  seed cut

- Efficiency  $\approx 99.96\%$
- Purity  $\approx 99.6\%$



First preliminary result from CERN test beam,  
129 GeV  $\pi$ ,  $33 \times 23.75$   $\mu\text{m}^2$  pixels

**position resolution  $\approx 2$   $\mu\text{m}$**



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## New DEPFET generation 'PXD5'

Mostly use 'baseline' linear DEPFET geometry

Build **larger matrices**

long matrices (full ILC drain length)

wide matrices (full Load for Switcher Gate / Clear chips)

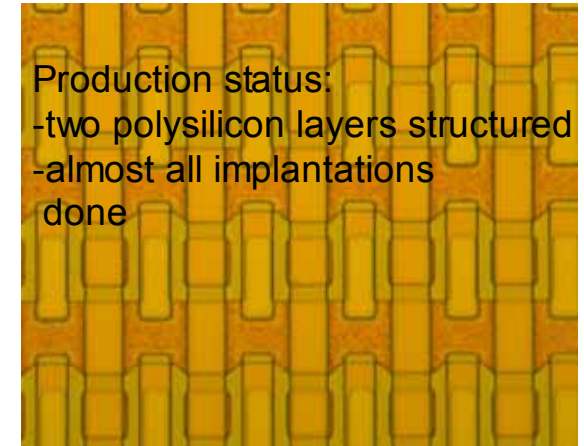
Try new DEPFET variants:

reduce **clear voltages** (required for radhard switcher technology)

(modified implantations, modified geometry)

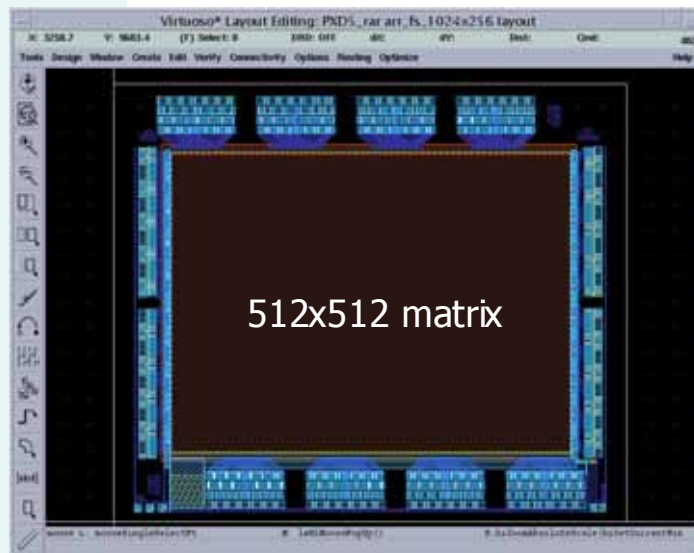
very **small** pixels ( $20\mu\text{m} \times 20\mu\text{m}$ , baseline:  $24\mu\text{m} \times 24\mu\text{m}$ )

Add some bump bonding test matrices



Production status:

- two polysilicon layers structured
- almost all implantations done



standard arrays  
compatible to  
existing hybrids

wide arrays  
( $512 \times 512$ , full ILC)

long arrays  
( $256 \times 1024$ ,  $\frac{1}{2}$  ILC)

various new  
standard arrays  
( $64 \times 256$  pixels,  
down to  $20 \times 20 \mu\text{m}^2$ )

Rainer Richter, MPI HLL

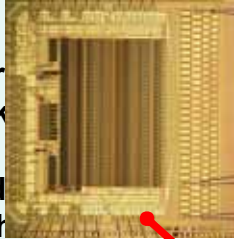
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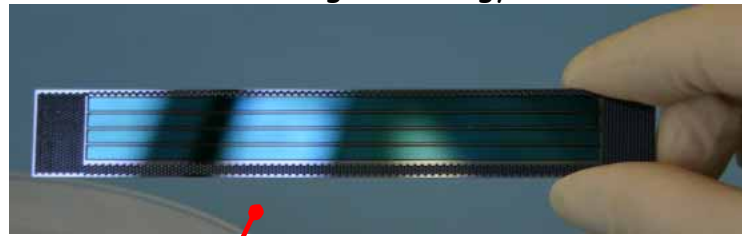


# The DEPFET ILC VTX Project

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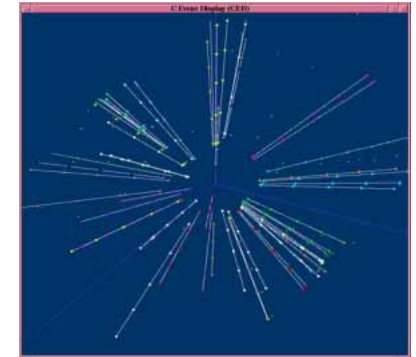


steering chips Switcher

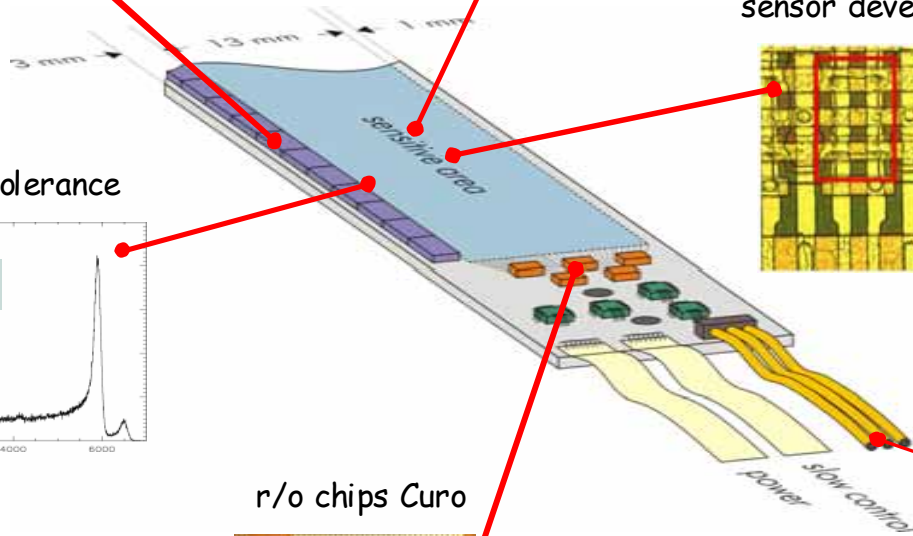
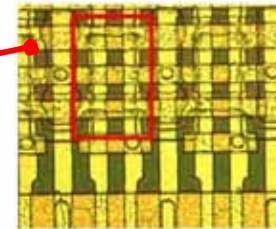


thinning technology

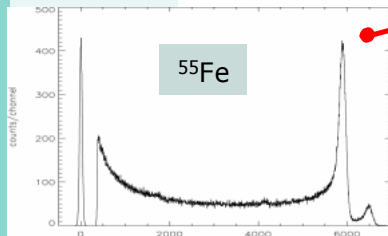
Simulation



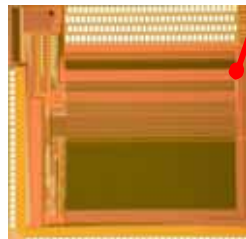
sensor development



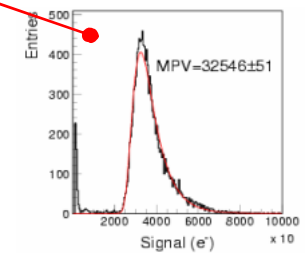
radiation tolerance



r/o chips Curo



beam test



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# Growing collaboration

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RHEINISCH-FRIEDRICH-WILHELMS-UNIVERSITÄT

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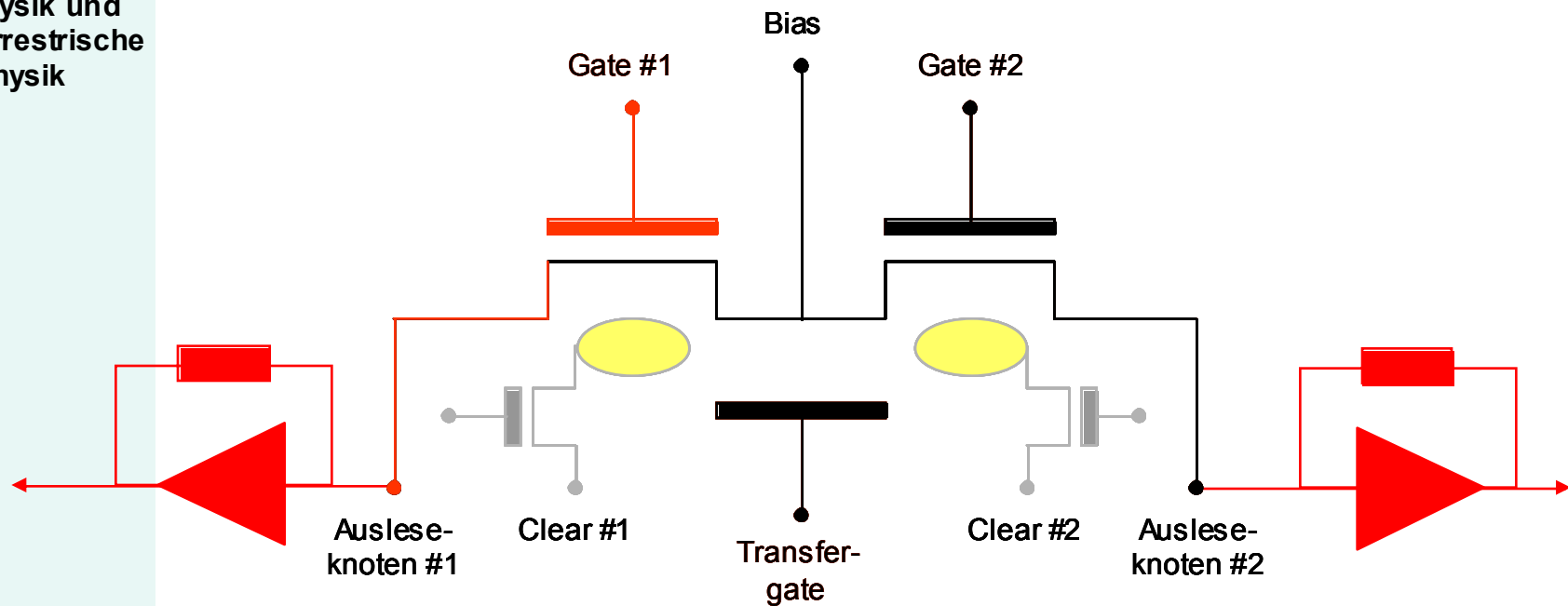
[www.depfet.org](http://www.depfet.org)



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# How to beat the $1e^-$ noise threshold

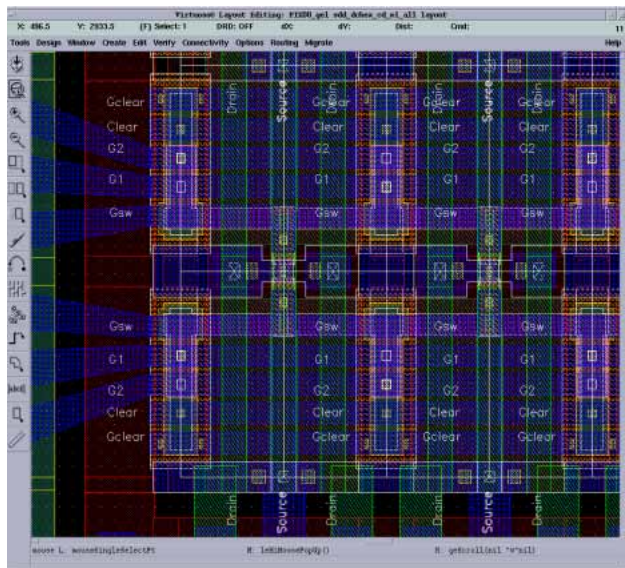
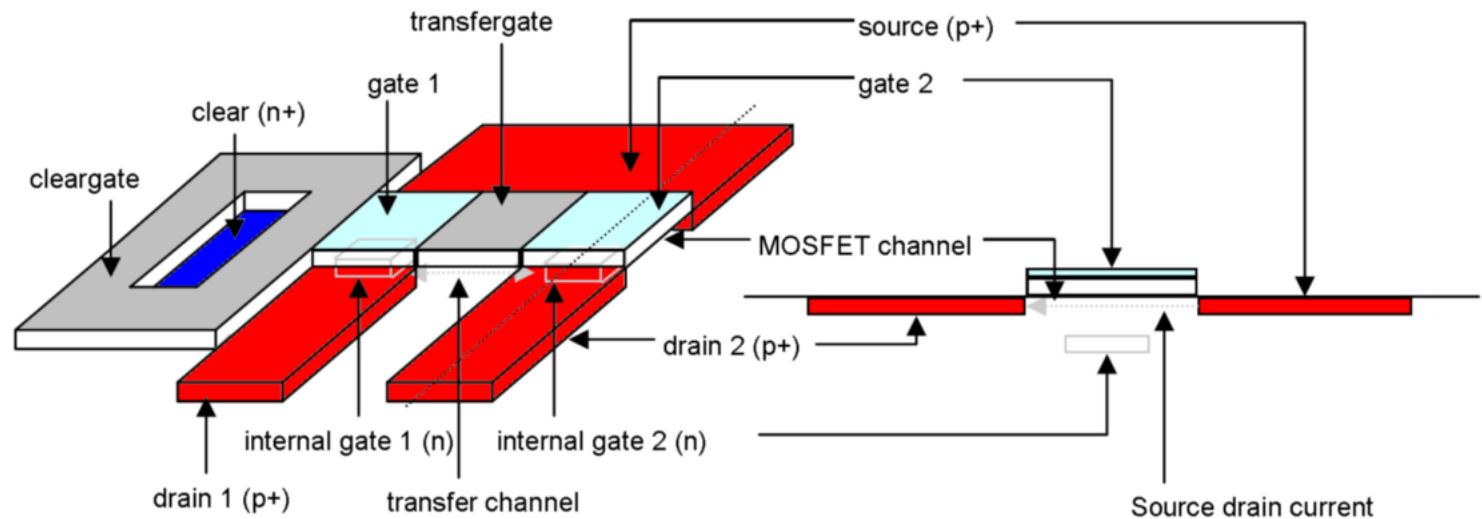
## RNDR (repetitive non destructive readout ) with DEPFETs – Principle





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## Realisation of a DEPFET- RNDR device



- » ILC-Type RNDR
- » Realised as a four by four Minimatrix

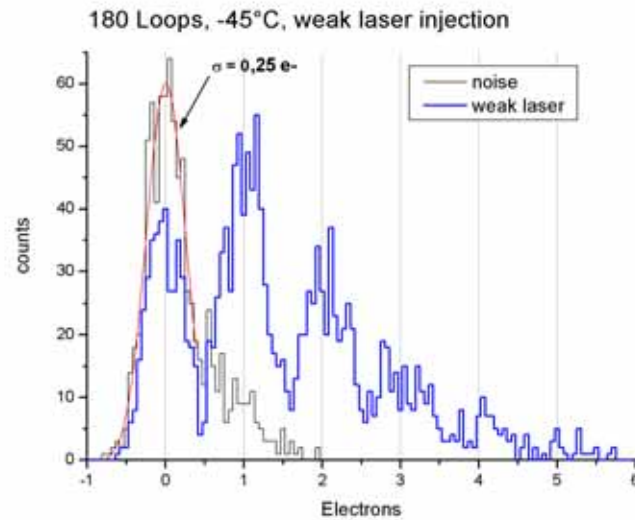
designed by G. Lutz

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## Laser spectra (S. Wölfel)



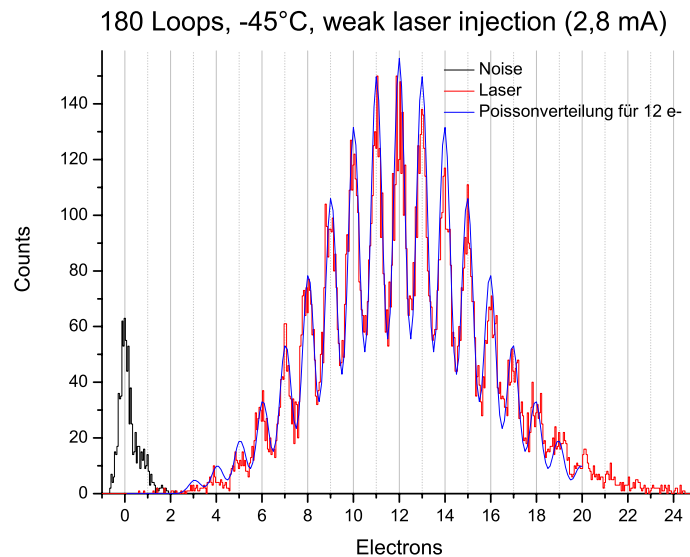
### Measurement:

Charge injection with laser during integration time

180 Loops for the readout (duration: 9.18 ms)  
-45 °C

Measured leakage current:

ca. 0,4 e- in 180 loops



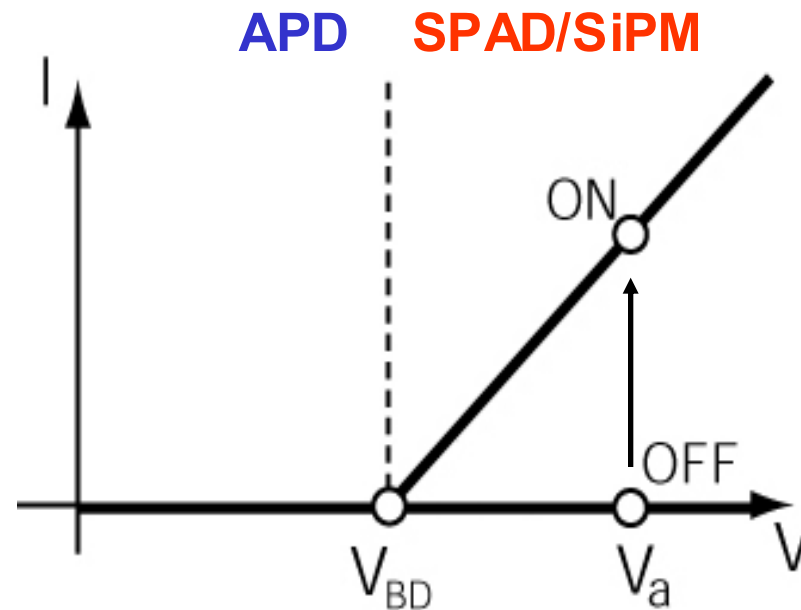
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## Avalanche PhotoDiode - Single-Photon Avalanche Diode

(after S. Cova)

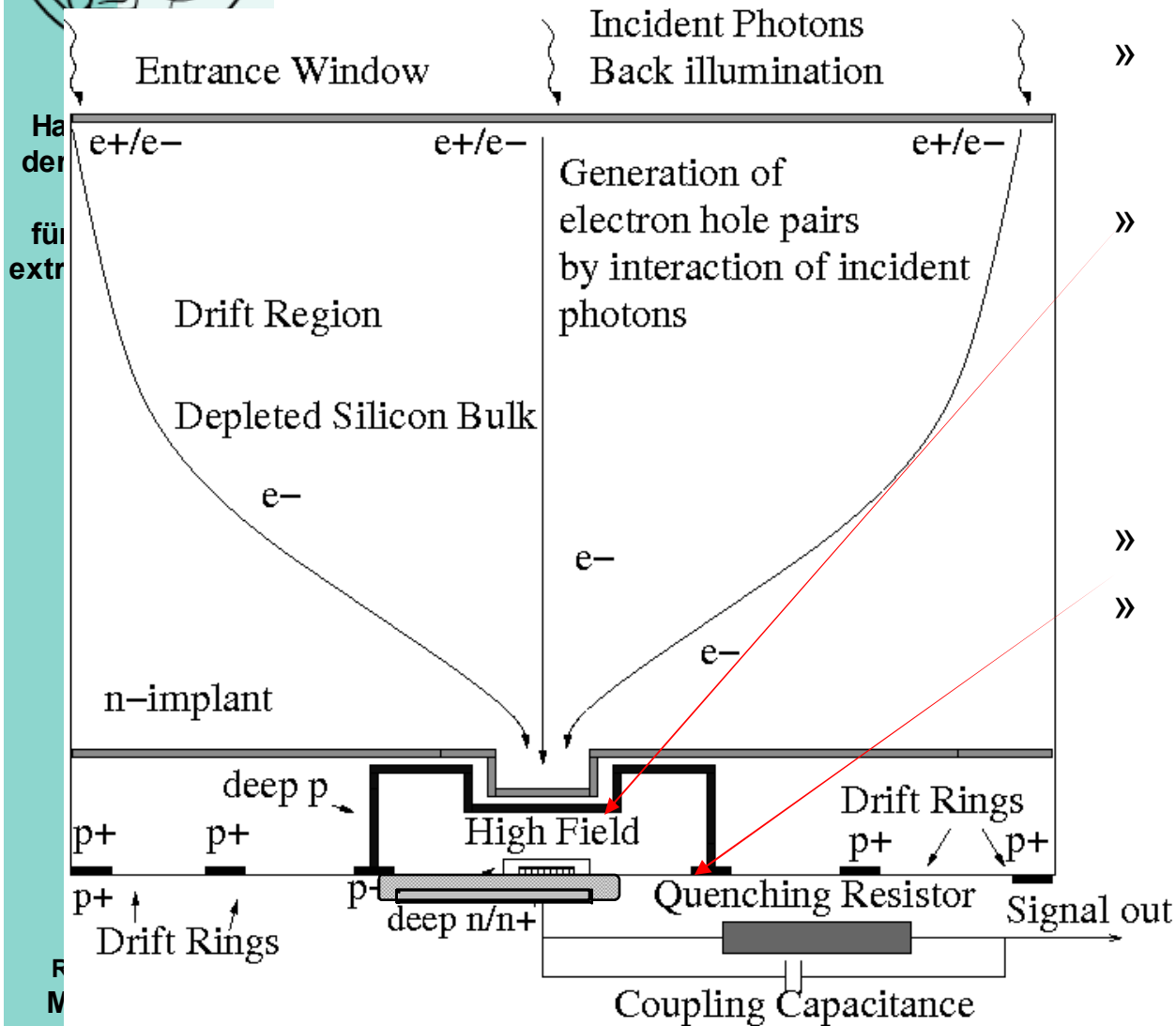


- Bias: slightly **BELOW** breakdown
- Linear-mode: it's an **AMPLIFIER**
- Gain: limited  $< 1000$
- Bias: well **ABOVE** breakdown
- Geiger-mode: it's a **TRIGGER** device!!
- Gain: meaningless ... or "*infinite*" !!

Array of SPADs connected in parallel  
to one readout node -> SiPM



# Concept of the BIDSiPM for high QE in the UV (MAGIC, EUSO, CTA)



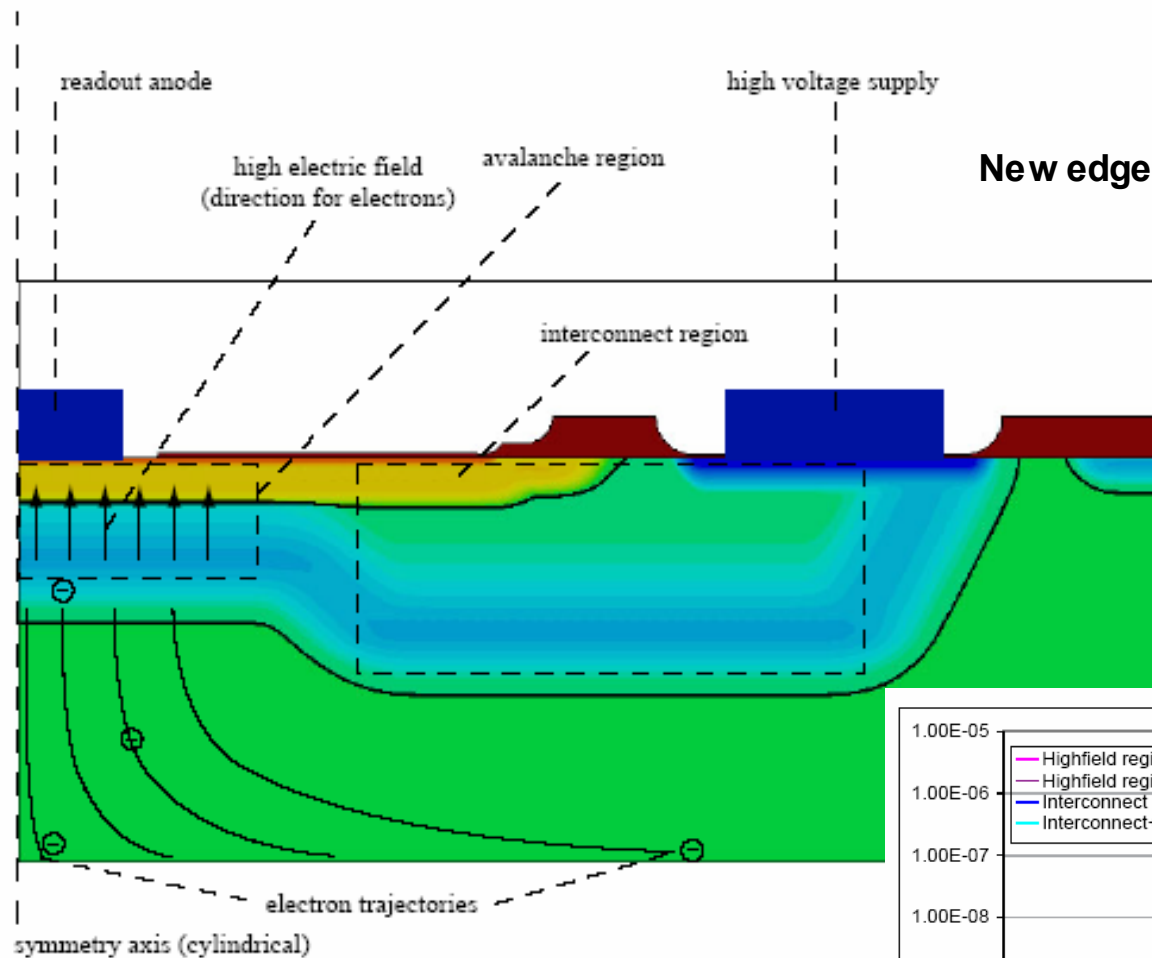
- » BIDSiPM combines principle of Drift Diode and SiPM
- » Modulated high field region necessary to avoid edge breakdown, modulated region has to be fully depleted for electron collection
- » Passive quenching
- » Combination of avalanche region with a drift region requires sideways connection of bias voltage for the avalanche region as amplifying unit



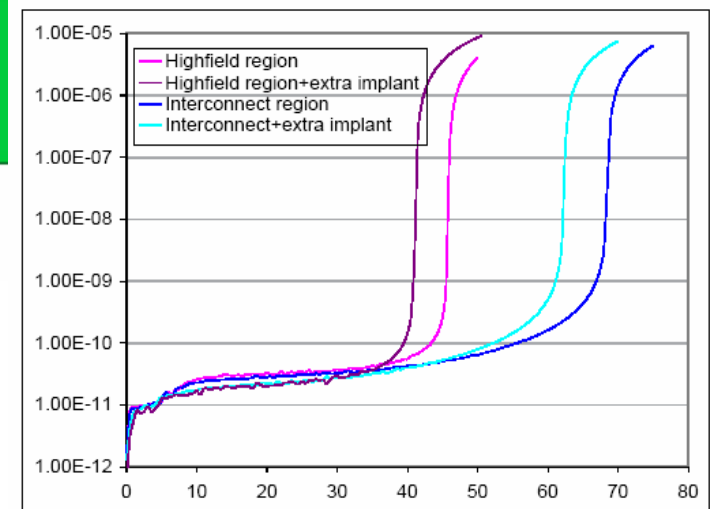
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# First Prototyping – single sided technology only



**New edge termination structure !**



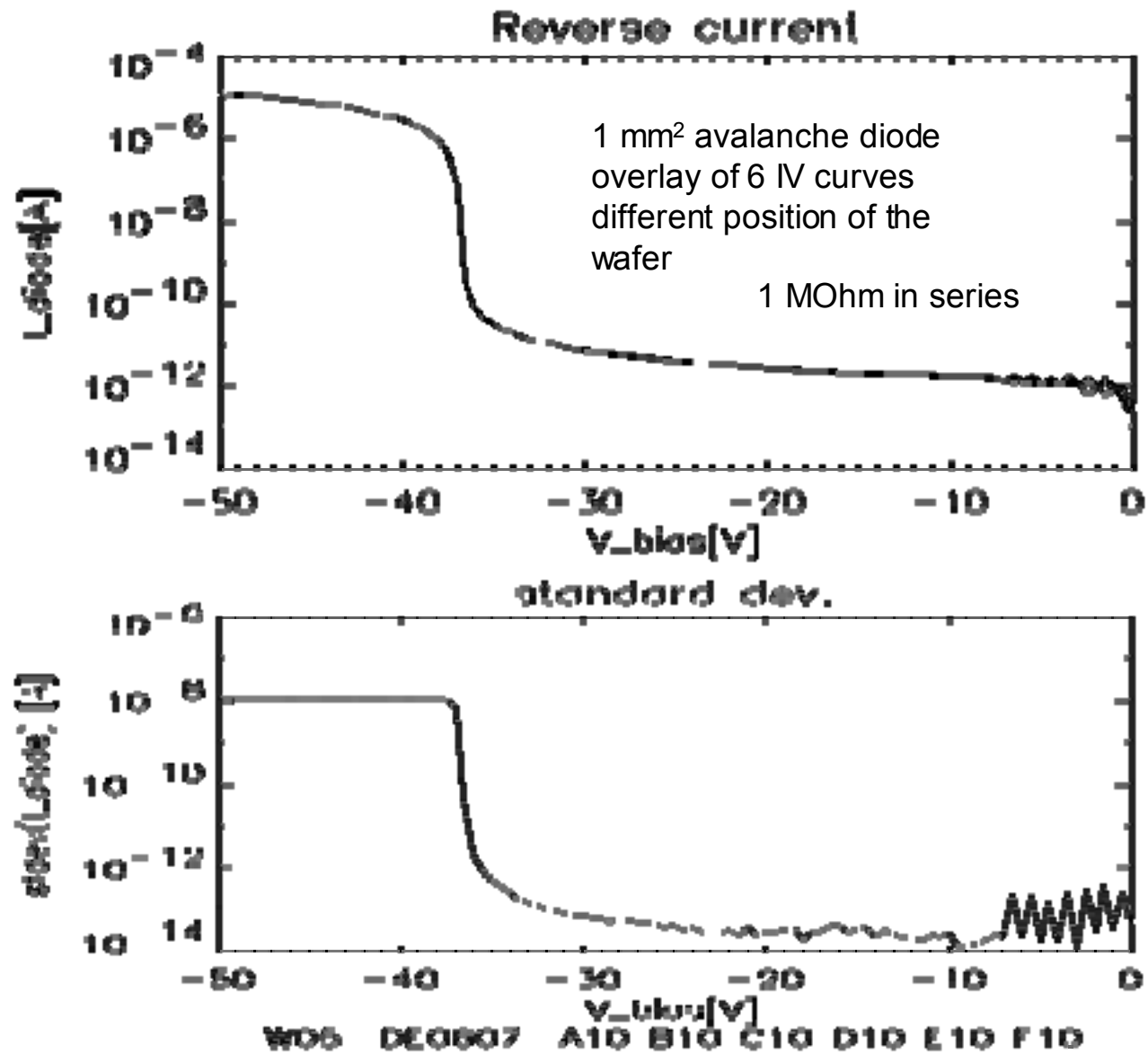




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## Uniformity of leakage current and breakdown voltage





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## Separation of Center and Edge Currents

Constant area: 1 mm<sup>2</sup>

Different circumferences:

4mm (6x)

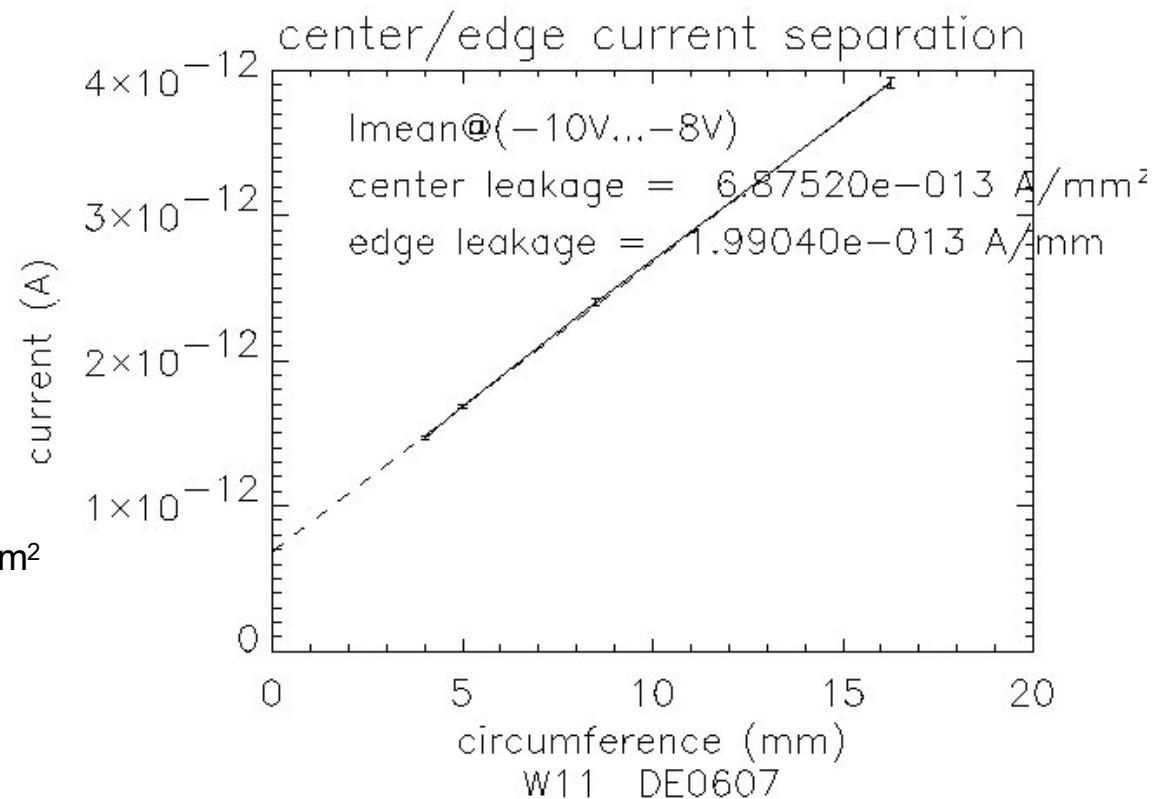
5mm(3x)

8.5mm(3x)

16.25mm(2x)

Leakage current

from the center ca. 0.5 pA/mm<sup>2</sup>



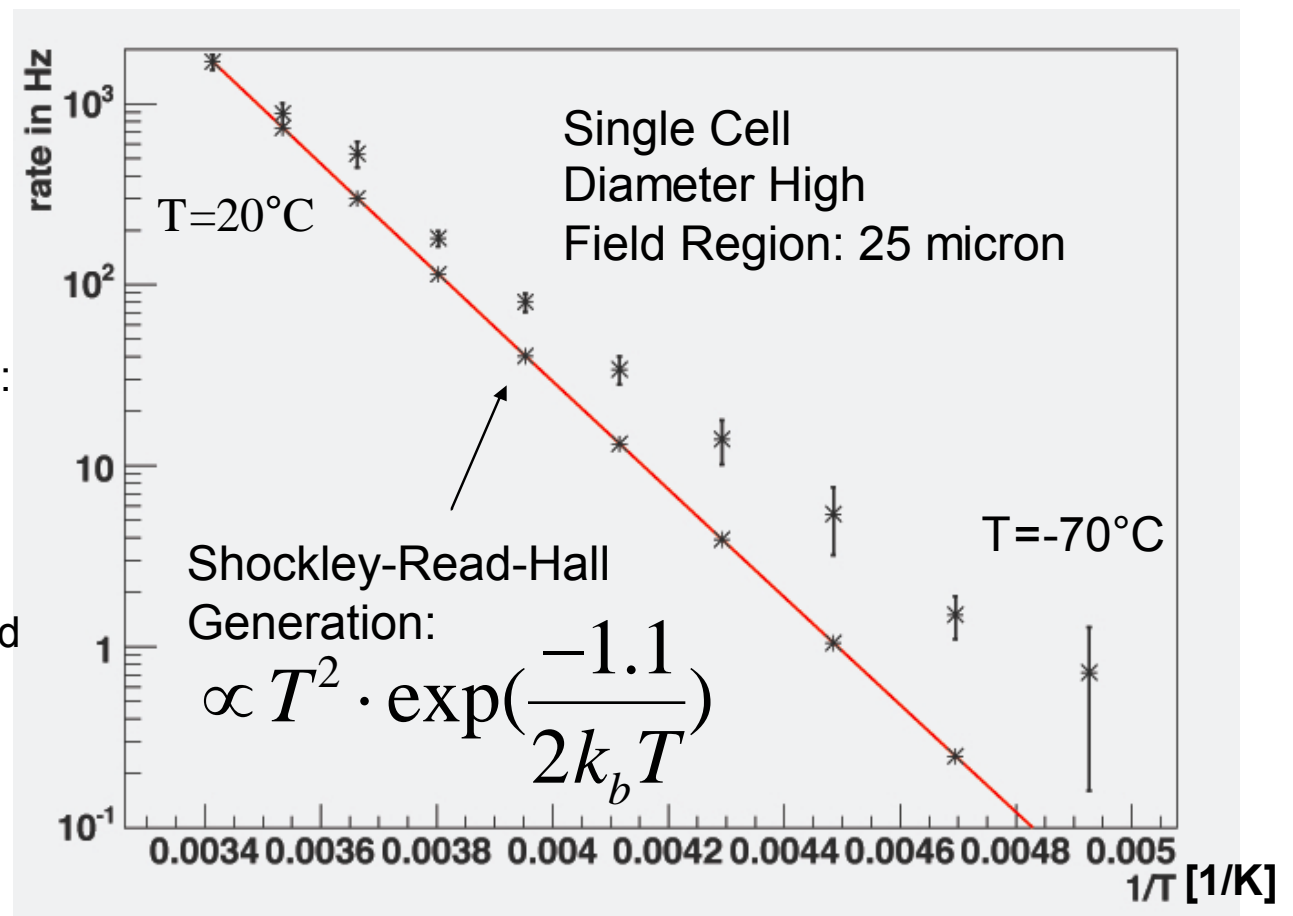


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## Dark Rate vs. Temperature

Rate for low  
temperatures  
higher than  
theoretically  
predicted from  
Shockley-Read-  
Hall Generation

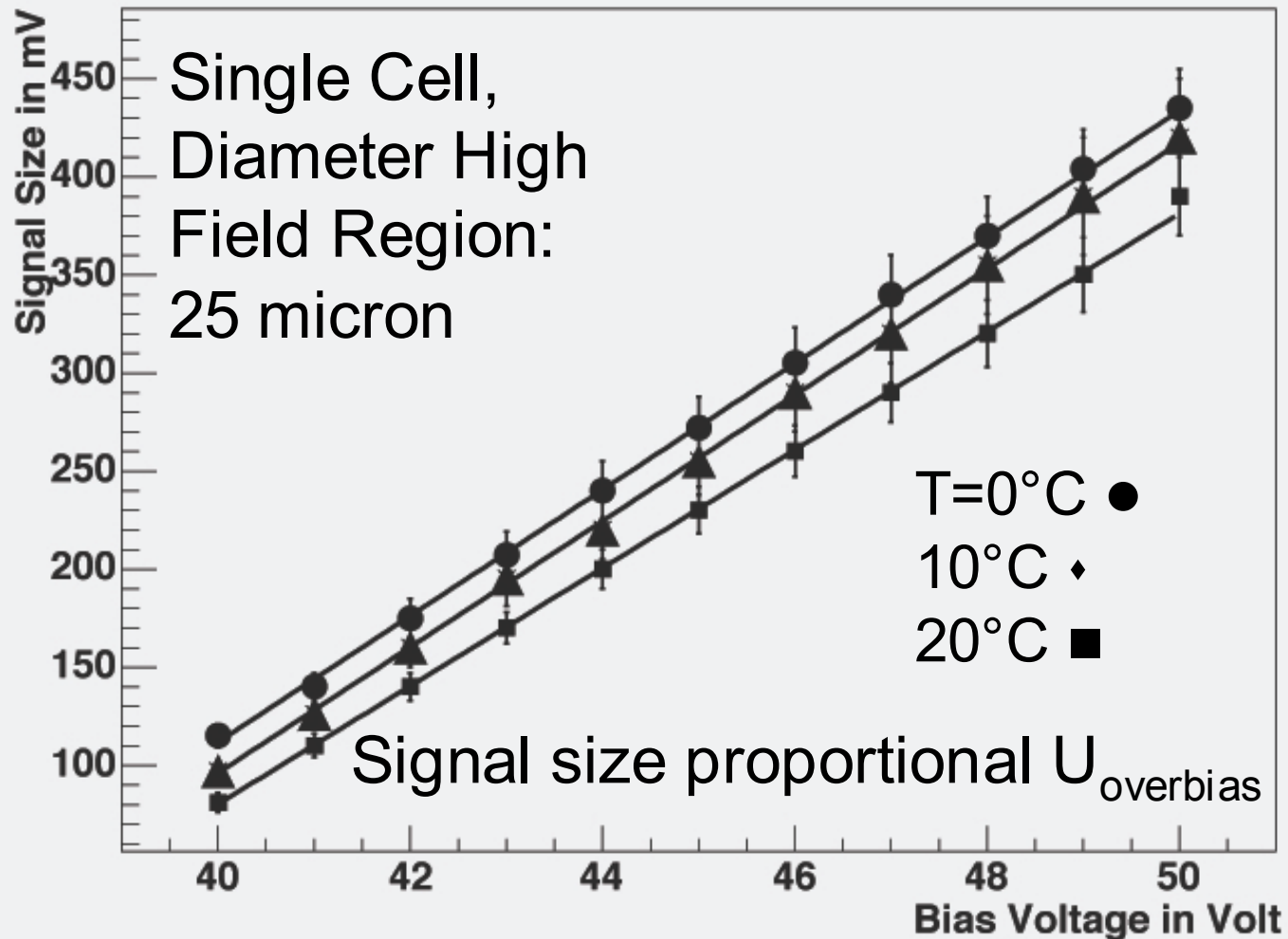
- Possible reasons:
- Traps  
->afterpulsing
  - diffusion of  
electrons  
into the high field  
region
  - tunneling





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## Signal Size vs. Bias Voltage

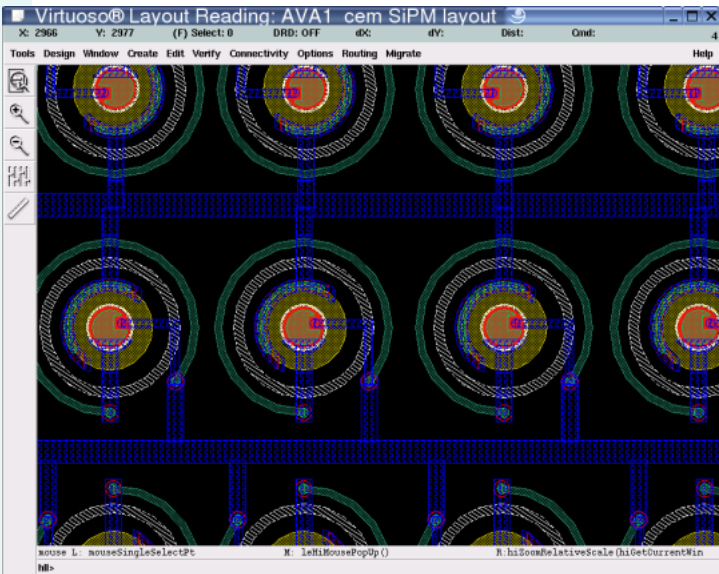
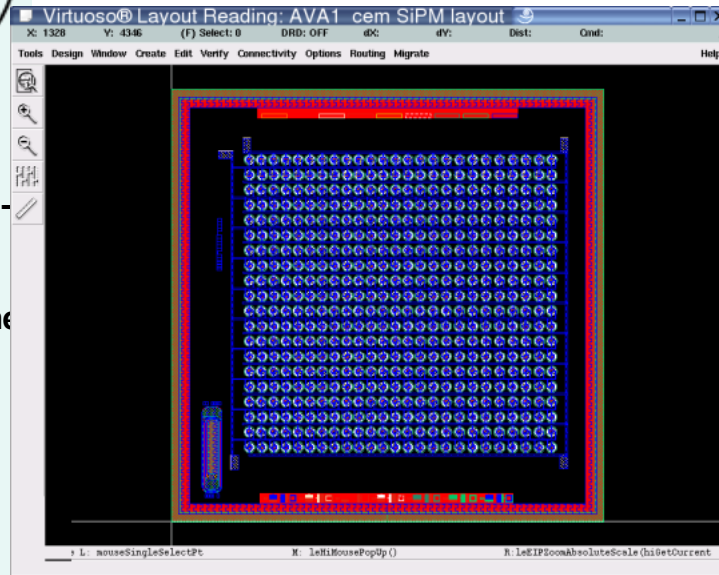




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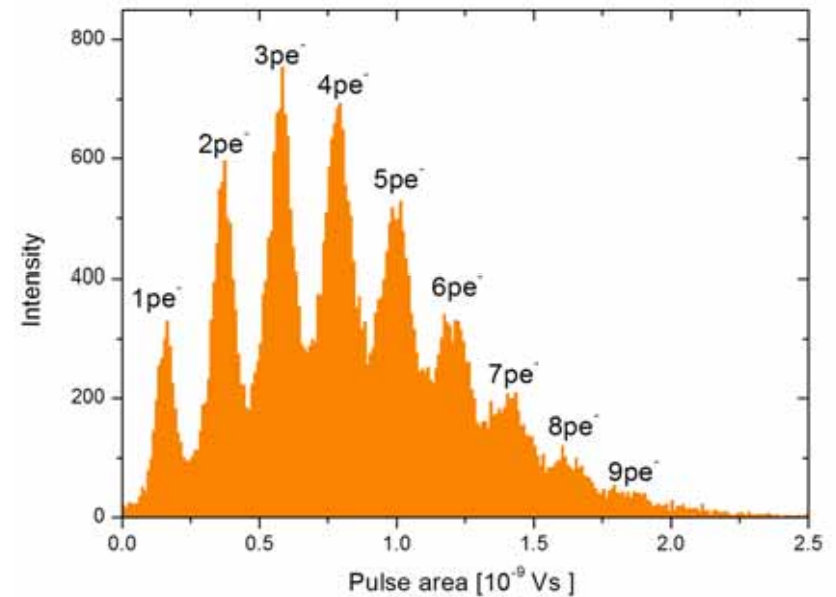
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# Photon spectrum



first prototype studies  
still with provisional means  
(implanted resistors instead  
of polysilicon ones)  
20x25 SiPM arrays

HF region  $R=12.5\mu\text{m}$   $\Delta V=4\text{V}$  laser (682nm 10ns width)





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## BIDSIPM - further steps

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Merge of Avalanche diode and Drift detector technology

-> backside illumination possible

Integration of readout network (quenching resistor and coupling capacitor) into each cell

Next production starts in February 07.

**Open issue:** optical crosstalk

Optical photons generated by the avalanche process itself trigger neighboring cells

Reduction of parasitic capacitances-> reduction of generated charge

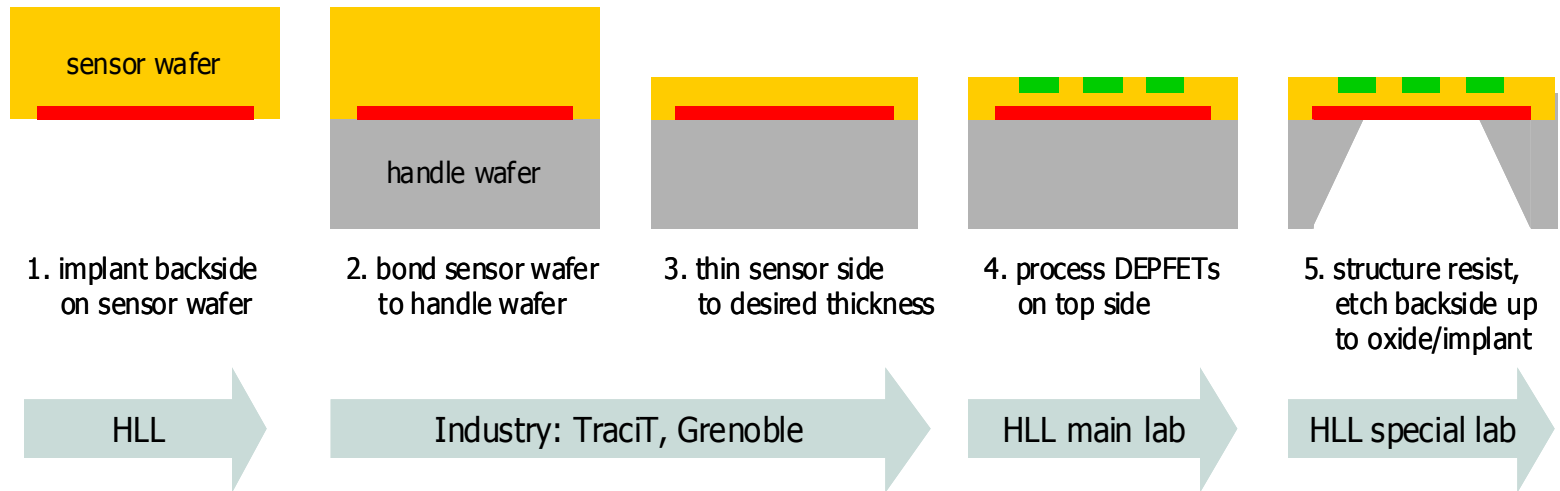
-> reduction of generated photons

If this is not enough: Optical insulation by V-groove etching becomes necessary.



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## Backside thinning – based on wafer bonding



» New: 150mm Ø wafers!

» New: Wafer bonding and thinning in industry

» New: Processing in HLL main lab

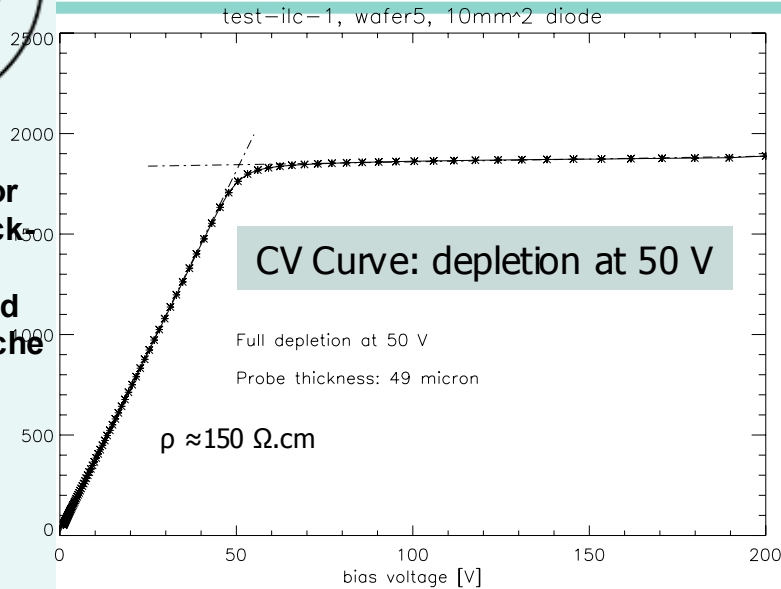
⇒ Still in R&D phase:

⇒ 1: process test structures on SOI wafers

⇒ 2: mechanical samples

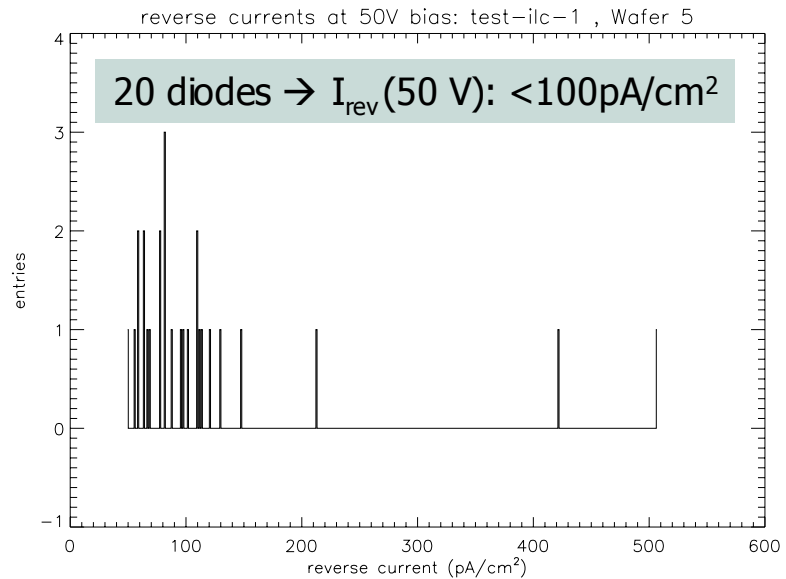
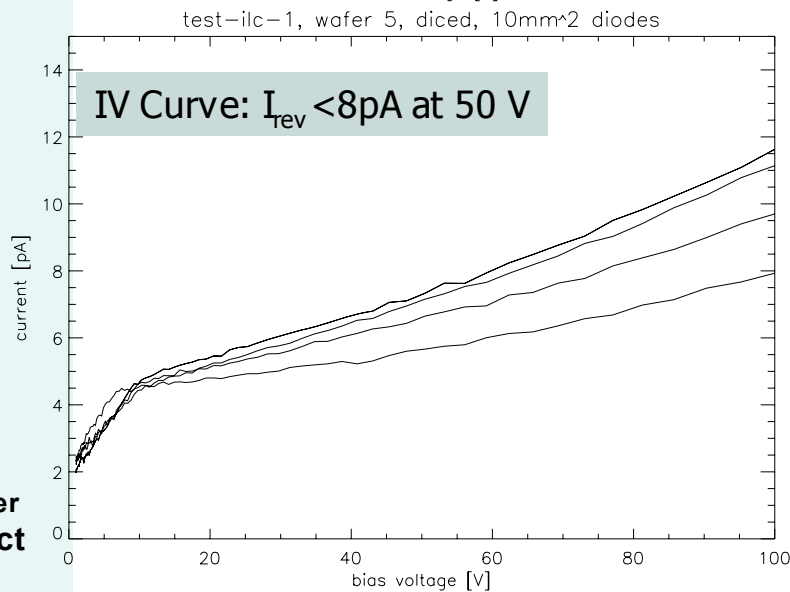


# PiN Diodes on thin Silicon



Thin diodes have excellent leakage currents.

Processing of the SOI wafers and removal of handle wafer does not degrade devices!





## Slide 24

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**rev2**

These are encouraging results not only for DEPFETs but also for our back illuminated avalanche diodes as we will see later  
rar, 12/16/2006

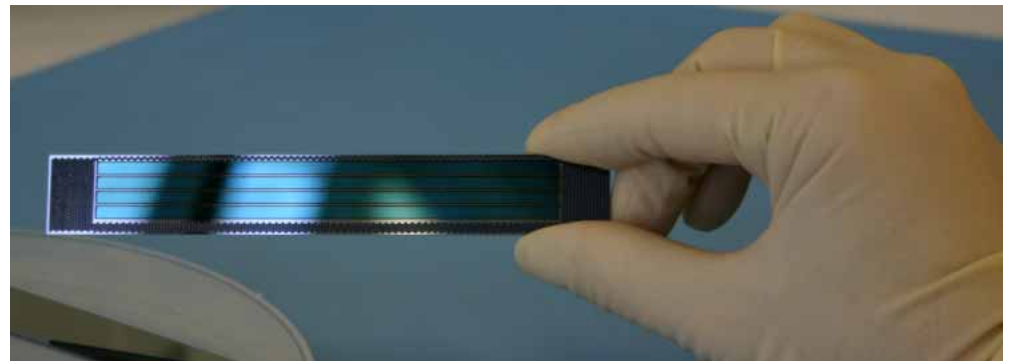
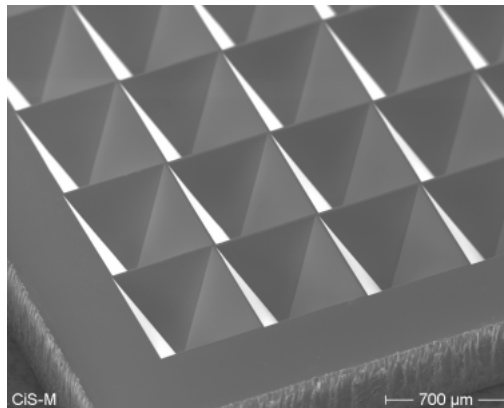
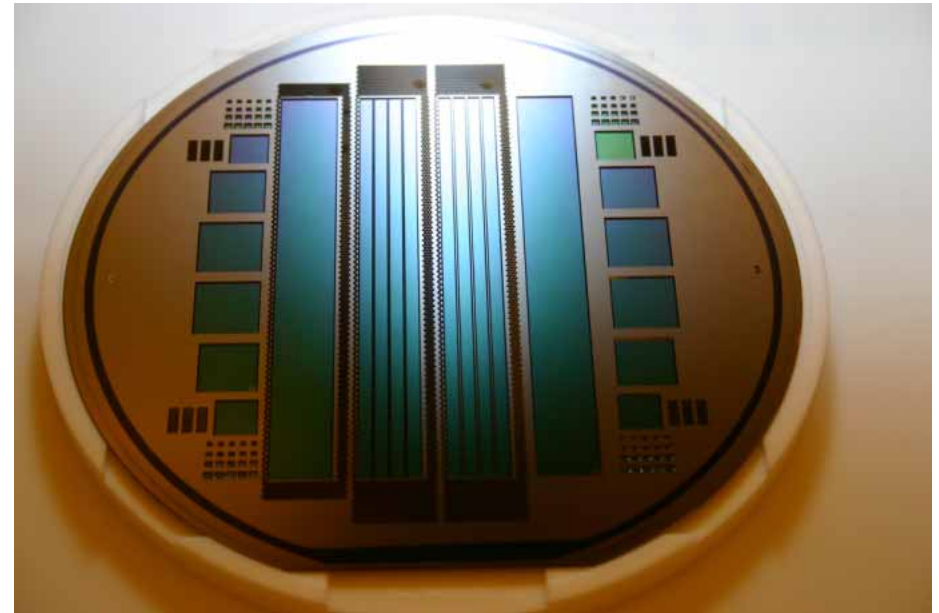


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# Prototypes

**Thin (50  $\mu\text{m}$ ) silicon  
successfully produced at  
MPI.**

- MOS diodes.
- Small strip detectors.
- Mechanical dummies.  
1.3 x 10 cm<sup>2</sup> plus  
stiffening frame &  
reinforcement bars.
- No deterioration of detector  
properties,  
keep  $I_{\text{leak}} < 100\text{pA/cm}^2$



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## R&D for a novel pixel detector for SLHC

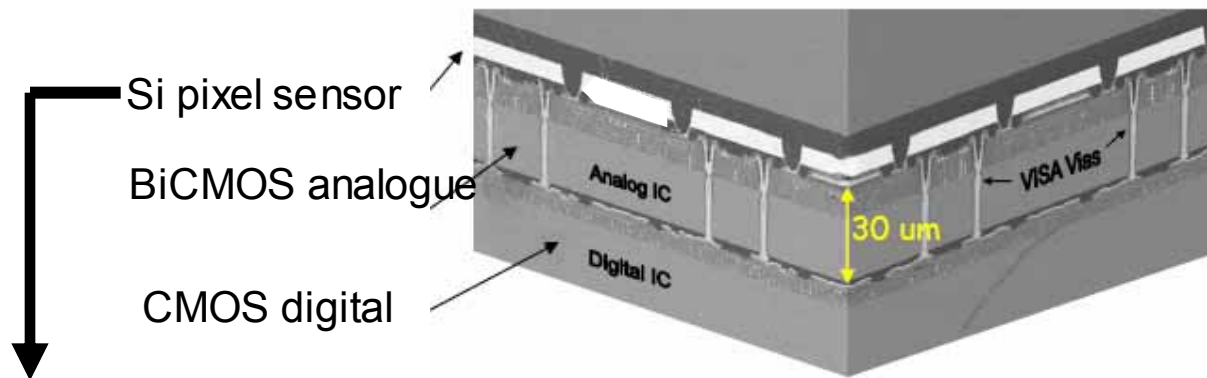
3D integration (sensor – electronics; electronics – electronics):

Alternative to bump bonding (fine pitch, potentially low cost?).

New possibilities for ASIC architecture (multilayer, size reduction).

Optimization of rad. hardness, speed, power.

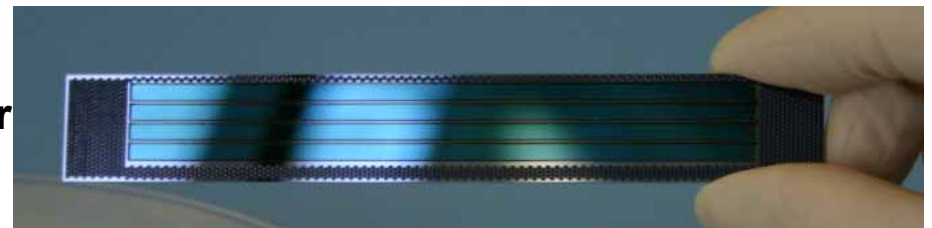
Impact on module design (ultra thin ASICs, top contact, 4-side buttable).



R&D on thin ( $O(50\mu\text{m})$ ) FZ silicon detectors:

Based on well known pixel sensor technology.

Can be operated at  $10^{16} \text{ n/cm}^2$  ( $V_{\text{dep}}$ ,  $I_{\text{leak}}$ , CCE).



Can lead to an advanced module design: rad hard with low material budget  
MPI will work with Fraunhofer IZM, Munich.



# Proposal for the LCLS+XFEL detector

devices are in preparation, fabrication ready: mid. 2007

The full sensitive area of the system is 59 cm<sup>2</sup> with 75 μm pixels, 1024 x 1024

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für Physik  
extrafest  
Physik

ADC



ADC

ADC

ADC

ADC



ADC

ADC

ADC

ADC



ADC

ADC

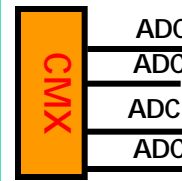
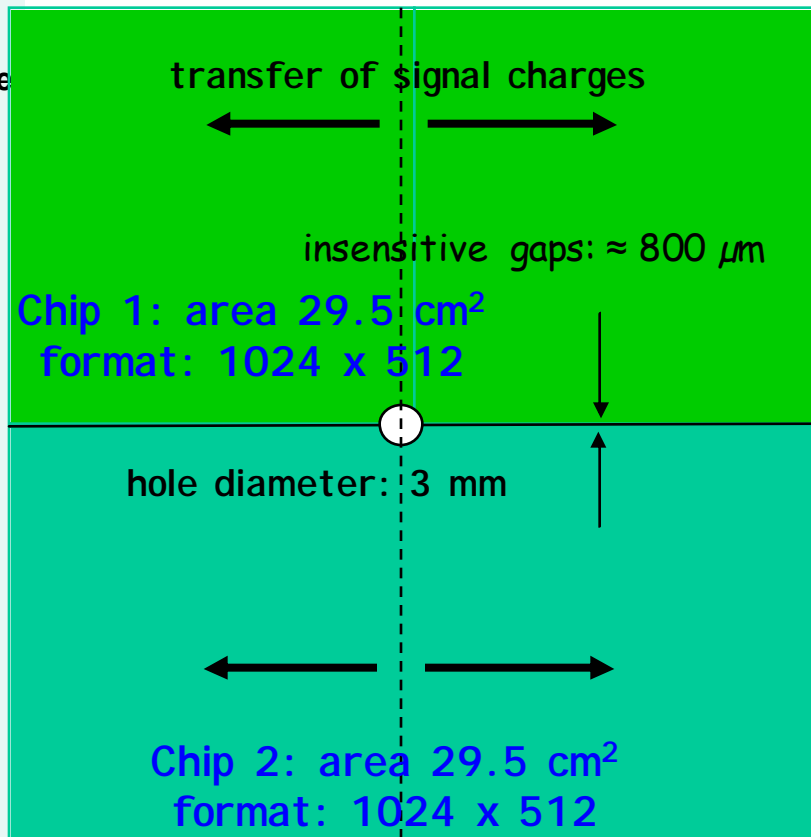
ADC

ADC



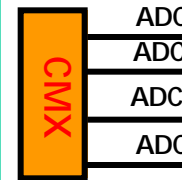
Rainer Richter  
MPA Project  
Review

18. 12. 2006



ADC  
ADC  
ADC  
ADC

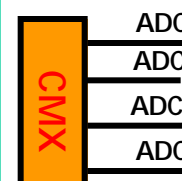
Full Frame imaging area per chip 512 x 1024



ADC  
ADC  
ADC  
ADC

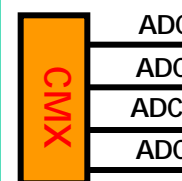
pixel size 75x75 μm<sup>2</sup>

total area per chip: 29.5 cm<sup>2</sup>



ADC  
ADC  
ADC  
ADC

readout time per frame: 4 ms i.e. 250 fps



ADC  
ADC  
ADC  
ADC

16 ADC outputs

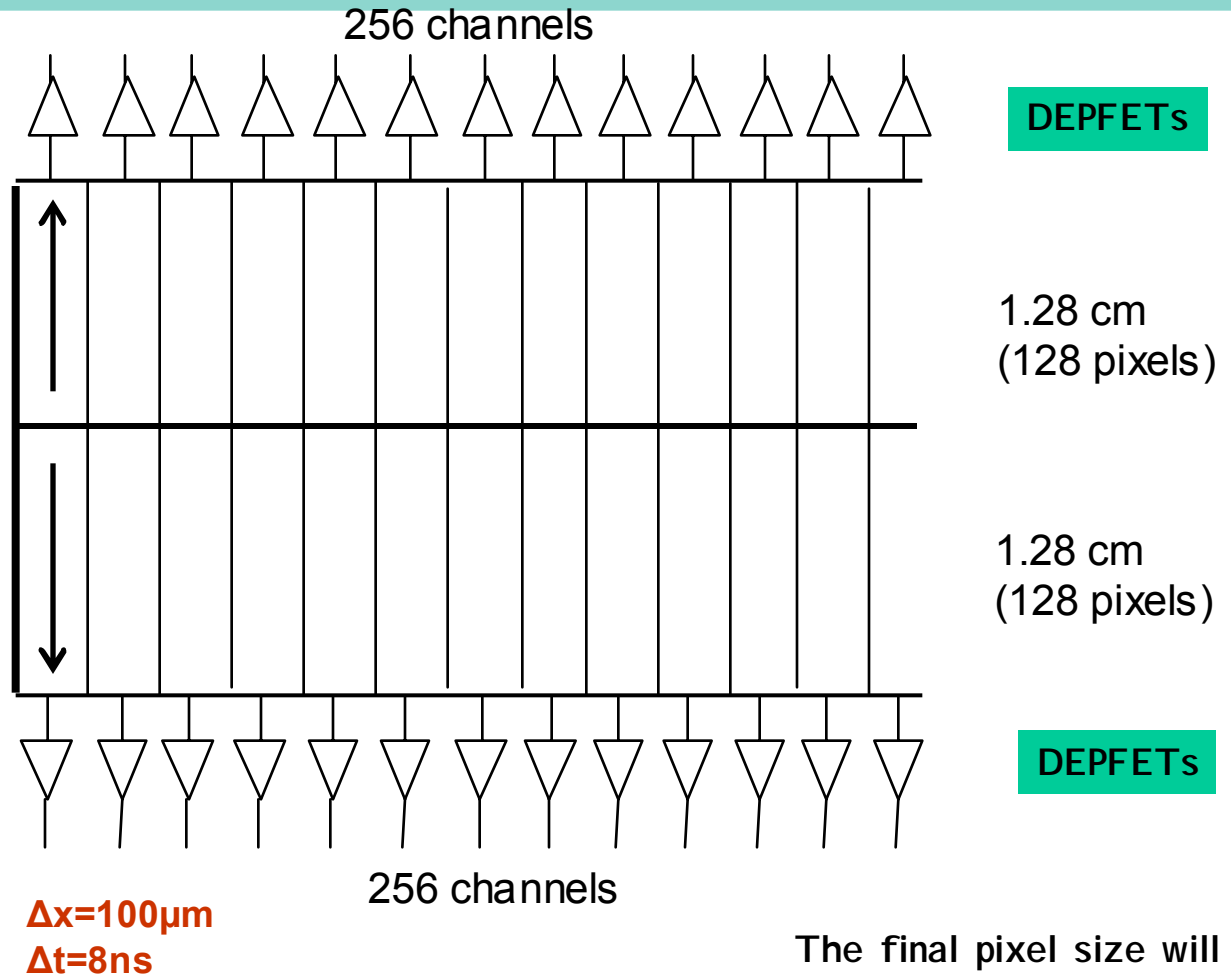
Total sensitive system area: 59 cm<sup>2</sup>



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## Device proposal for the XFEL: CDD+int. frontend (phase I, prototyping)

256x256  
2x256 channels  
1 MHz  
100 $\mu$ m pixel  
room temp.  
10<sup>3</sup>-10<sup>4</sup> X-rays  
QE>80%@10keV  
ENC<30 el.  
Expandable to:  
512x512  
1024x1024  
(no dead area)



drift velocity calibration  
with electron injectors

$V_{\text{drift}} \approx 13\ \mu\text{m/ns}$  (i.e.  $\sim 3.5\text{V}/30\mu\text{m}$  bias)  
 $T_{\text{drift, max}} = 1000\ \text{ns}$



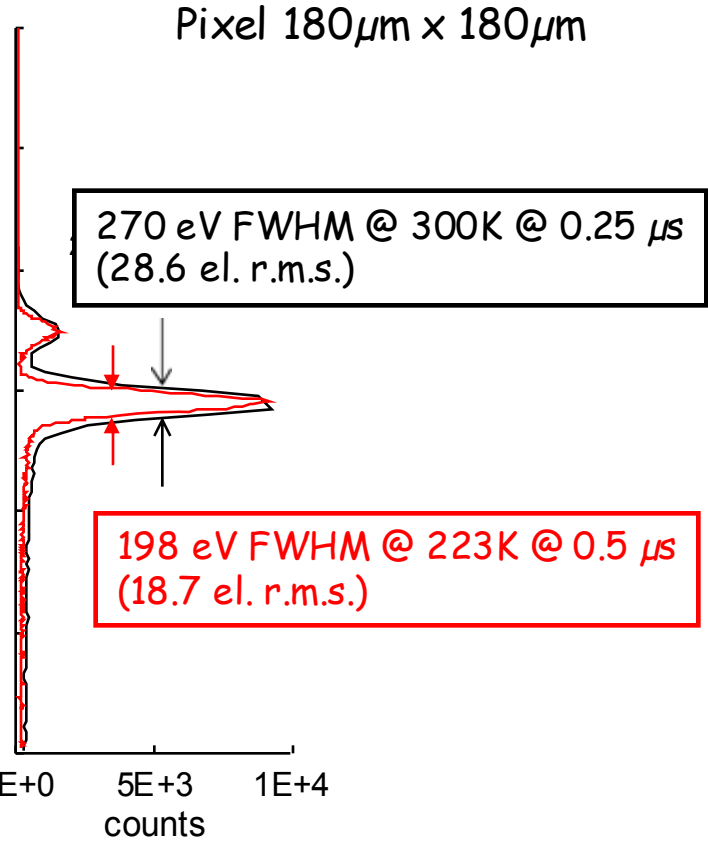
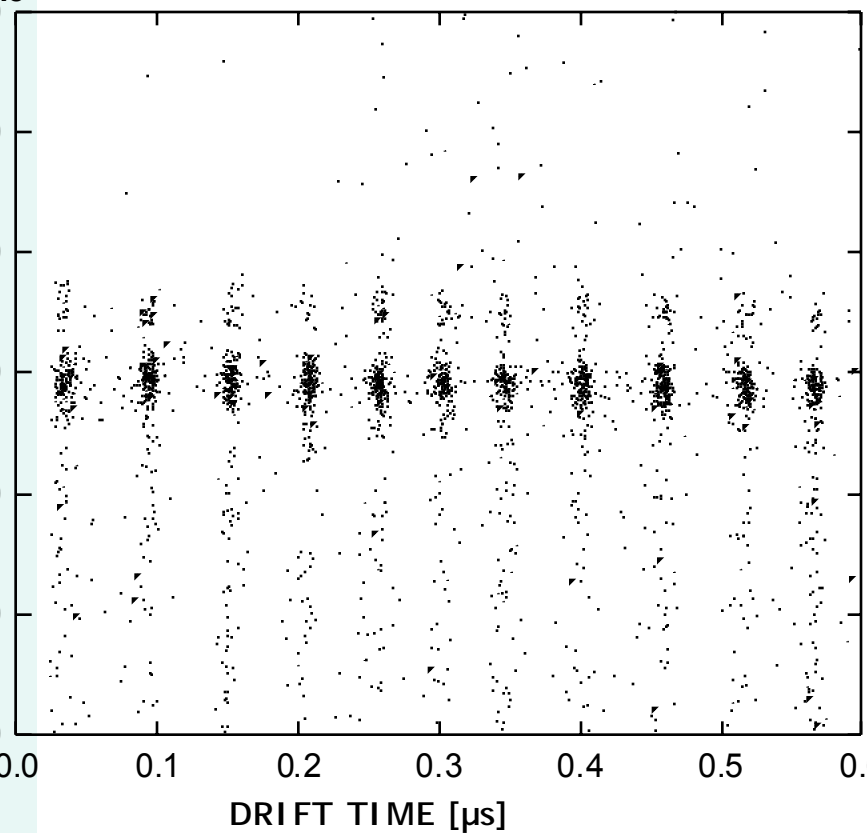
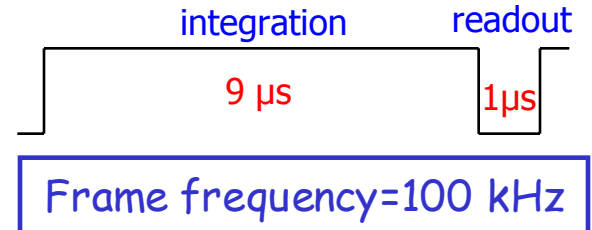
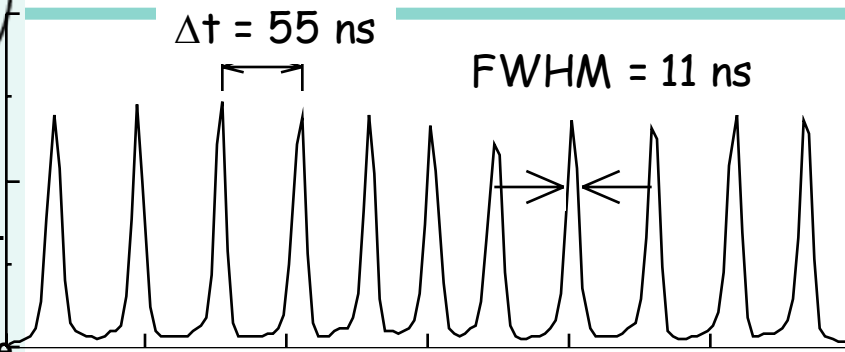
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ENERGY [eV]

Rainer Richter  
MPI - Project  
Review  
18.12.2006

# Imaging and spectroscopy of a Fe-55 source @ 100 kHz

A.Castoldi, C.Guazzoni, P.Rehak, L.Strüder, et al, Trans. Nucl. Sci. 49 (3) June 2002





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## Detector technologies and Projects

- **DEPFET** – ILC, Bepi Colombo, Symbol-X, XEUS, XFEL
  - **RNDR with DEPFETs**
- **pn-CCD** – eRosita, XFEL  
**Si Drift Diodes, XFEL**
- **Avalanche photodiodes**  
**Si Photomultiplier (BIDSIPM) - MAGIC, EUSO, CTA**  
**AA-pnCCD - HTRA**
- **Thinning Technology** – ILC, MAGIC, SLHC
- **Back thinning based on wafer bonding becomes a key technology for many projects!**

## Projects at the MPI Semiconductor Laboratory

(Stand: November 2006, LTS,)

<b>MPE main project</b>
<b>MPE project</b>
<b>HLL project</b>
<b>MPP main project</b>
<b>MPP project</b>
<b>MPE &amp; MPP project</b>
<b>CFEL project ASG of MPG</b>

Present projects	Institute	Physics goal	Basic method	Semiconductor device	Status	Funding	Perspectives
<p>XEUS (X-Ray Evolving Universe Spectrometer)</p> <p>The wide field imager</p>	<p>MPE</p> <p>ESA</p> <p>(LU ?)</p>	<p>First massive black holes.</p> <p>First galaxy groups and their evolution into the massive clusters</p> <p>Evolution of heavy element abundances.</p> <p>Intergalactic medium using absorption line spectroscopy.</p>	<p>Large area X-ray mirror telescope with a large area silicon detector</p>	<p>Thick DEPFET-pixel detector</p> <p>sensitive thickness: 500µm</p> <p>Format: 1024 x 1024 pixel</p>	<p>First small size prototypes produced and under test</p> <p>System test starting in beginning of 2004</p>	<p>TRP contracts with ESA:</p> <p>2001: 300 k€</p> <p>2002: 550 k€</p> <p>2003: 550 k€</p> <p>2004: 550 k€</p> <p>2006: 150 k€</p>	<p>XEUS will get additional funding in 2005 and 2006</p> <p>XEUS is still on the ESA agenda with high priority</p>



eROSITA	MPE ROSK DLR ESA	All sky X-ray survey	X-ray mirror telescope of same construction as in DUO	Same as in DUO  pixel size: 75·75 $\mu\text{m}^2$	Same as in DUO	248 k € in 2006	launch: 2011, mission approved
SIMBOL-X	MPE Saclay Brera IAAT Tsinghua	X-ray astronomy	Macropixel detector in focal plane of X-ray mirror telescope	Macro-pixel-detector (combination of drift detector and DEPFET)	In production on the MEGA wafers	No funding	Project no yet approved by nat. funding agencies
BepiColombo	MPE MPI LUniv	planetary science, Processes and chemical composition of Mercury	Imaging optics – scanning – with spectroscopic X-ray detectors	Macropixel detectors	MM; EM, QM, FM, FS actually in production	220 k€ by ESA approved, 700 k€ promised by ESA, 750 k€ requ. by MPI L.	
XMM “consulting”	MPE ESA	Early universe, diffuse X-ray background, etc.	Wolter type X-ray telescope, X-ray CCD	Full frame pn-CCD	launched in 1999 - operational	no funding	operation guaranteed up to 2010
HTRA, old High Time Resolution Astrophysics	MPE MPIA MPA Opticon	Observation of rapidly varying objects	Optical ground based telescopes  4 – 8 output nodes	pn-CCD  pixel size: 51·51 $\mu\text{m}^2$	Produced together with DUO	no funding	More systems will be needed at a later stage
HTRA new High Time Resolution Astrophysics	MPE MPIA MPA Opticon	Observation of rapidly varying objects	Optical ground based telescopes  4 – 8 output nodes	AAPn-CCD  pixel size: 48·48 $\mu\text{m}^2$	Produced together with AAPnCCDs and BIDSiPM	from 2004-2006 500 k€ through OPTICON in EU – FP6, ESO	More systems will be needed at a later stage
XEUS: The fast timing detector	MPE CESR ESA	Fast timing observation of bright X-ray sources	SDD in focal plane of XEUS wide field imager	Silicon drift detector array, 19 cells	Prototypes produced together with SIDDHARTA	Up to now: No funding	Decisions: Upon approval of XEUS through ESA
Hard X-ray detector	MPE	High energy X-ray detection up to 200 keV	Scintillator readout with SDDs	Silicon drift detector arrays	In production	Up to now: No funding	Project MAGIC discontinued at MPE
Mars Mission EXOMars	MPE MPI Che. Uni Mainz ESA	Marsian geology	Mößbauer strectrometry, XRF	circular SDDs	proposal phase PI: Univ. Mainz (Klingelhöfer)	funding through University of Mainz	similar to the previous NASA Mars mission

Wide Field camera from IR to X-rays	MPE MPQ LMU EXcluster	Attosecond lasers for table top light source	Qualification of test set up	pnCCD 256 x 256 50 or 75 $\mu\text{m}$ pixel size	Project <b>approved</b> devices are operational	250 k€ from DFG thru LMU thru EXcluster	More systems needed for the same type of experiments
BIB Detektoren	MPE, IR	IR astronomy	Silicon BIB detector up to 300 $\mu\text{m}$	pn diodes on epi silicon	preliminary study	none	not yet discussed with RG
Front-end electronics  DLR - First chance	MPE, DLR	Development of commercially useful frontend ASICs	Arrays of parallel amplifiers with MCDS and gaussian shaping	CAMEX and ROTOR type devices	contract end in march 2004, extension possible up to 2006	2002: 125 k€ 2003: 125 k€ 2004: 40 k€	abgeschlossen
ESA Scint	MPE, Politecnico di Milano	basic technological tests	Gamma spectroscopy	SDDs coupled to scintillators	design, fabrication	ESA funding: 30 k€	subcontractor of Politecnico di Milano
Sensors for adaptive optics, wave front sensors	MPE ESO Opticon	Rapid corrections for change of atmosphere	4 – 8 output nodes, Reduction of readout capacitance, low noise required	pn-CCD pixel size: 51·51 $\mu\text{m}^2$  No Reset implemented	Produced together with DUO	Total return through PNSensor: 140 k€	If successful in 2007, 15 systems needed
SIDDHARTA	MPE Frascati Wien	Investigation of kaonic atoms	X-ray spectrum and lifetime	Drift detectors ~200 of 1cm <sup>2</sup>	fabrication start July 2004	Funded through EU FP6; PNSensor + HLL: 498 k€	Start of the experiment in 2005
DRAGO	MPE Politecnico di Milano	Medical imaging	Combination of CsI crystal with multicell SDD	Multicell Silicon drift detector	In production on MEGA wafers. Process finished: March 2004	65 k€ through INFN to PNSensor for layout and simulation	
FELIX	MPE Milano	X-ray fluorescence (art)	Direct detection of radiation	Silicon drift detectors	In production on MEGA wafers	25 k€, through INFN to PNSensor for layout and simulation	Project finished in 2006

## Projects under the umbrella of ASG and CFEL (MPE+MPP)

XFEL Detector LSDD	MPE, Uni Mannheim CFEL, DESY, Uni Siegen, etc.	Structure of solids, molecule imaging, chemical reactions	Diffraction and scattering experiments at synchrotrons	CDDs terminated with DEPFET amplifiers, CMOS electronics development	conceptual design study,  prototype development	Funding through XFEL GmbH, 10 participating institutions recommended for funding from 2007-11 total: 7 ME	Nutzer XFEL Hamburg, CFEL
FLASH detector systems	MPE, Uni Siegen DESY	Structure of solids, molecule imaging, chemical reactions	pump-probe x-ray ph.correlation coherent diffraction and single particle imaging	pnCCD detector system	“small” pnCCD system, 384x384  tests and experiments @ DESY	funding through DESY (300 k€) not yet approved !	
pnCCD Camera for PETRA III	MPE, CFEL DESY Uni Siegen	Structure of solids, molecule imaging, chemical reactions	pump-probe x-ray ph.correlation coherent diffraction and single particle imaging	pnCCD detector system	1024 x 1024 format	funding through DESY (1.800 k€) not yet approved !	
LCLS Detector	MPE, CFEL DESY Uni Siegen	Structure of solids, molecule imaging, chemical reactions	pump-probe x-ray ph.correlation coherent diffraction and single particle imaging	pnCCD detector system	1024 x 1024 format	funding through CFEL, 3.100 k€ APPROVED !	

Present projects	Institute	Physics goal	Basic method	Semiconductor device	Status	Funding	Perspectives
ILC Vertex detectors	WHI Bonn Prag Berkeley	e+e- collider physics	Thin fast vertex detector	Thin DEPFET pixel detector	Thick detector prototypes produced. Thinning technology developed	2002: 45 k€ 2003: 45 k€	Funding(BMBF) discontinued  TESLA (or any LC) is still under study
SLHC LHC Upgrade	MPP, ATLAS Team	Higg's spectroscopy	Particle detection and reconstruction identification HEP detector	silicon strip detector, thinned,  luminosity increase	Start of concept development  Exp. start: 2013	none	major future high energy physics experiment
EUSO and successors	WHI and others	Very high energy cosmic ray observation	Observation of showers in atmosphere from space (ISS)	Back side illuminated avalanche detectors	Concept being developed	No funding	Project no yet approved by nat. funding agencies
MAGIC, CTA SiPMs and successors	WHI	Very high energy air shower detection	Imaging of fluorescent and Cerenkov light with SiPMs	Avalanche embedded Silicon Drift Detectors operated in Geiger mode	Design, Fabrication of first test structures	Funding thru MPG Grossgeräteantrag: approx. 250 k€ to PNS	Potential candidates for HESS and other low light level applications
GERDA	MPP MPI-KP	neutrinoless double beta decay		Ge detectors	pending	none	
Muon collider	WHI	Accellorator development	Muon capture cross section measurement	Silicon drift detectors	Test samples of SDDs delivered	Up to now: No funding	Funding through BMBF envisaged at later stage
Radiation damage	MPP, RD50	Understanding, modelling of RD	solid state analysis before and after RD	Diodes , SSDs	in progress	none	ongoing activity

ATLAS ``consulting``	WHI and others	Higgs spectroscopy, test QCD, etc..	Vertex detection	radiation hard silicon strip detectors	development completed, module test ongoing, test	no funding	first data from LHC in 2007
CAST (Cern Axion Search Telescope)	WHI MPE CERN and others	Search for solar axions with an X-ray telescope	Wolter-type X- ray optics, pn- CCD in the focus	pn-CCD (XMM type, or later DUO type)	Operational since 2002	2002: 99 k€ 2003: 99 k€ 2004: 99 k€	Upgrade foreseen in 2004/2005 (Helium inside the magnet volume)

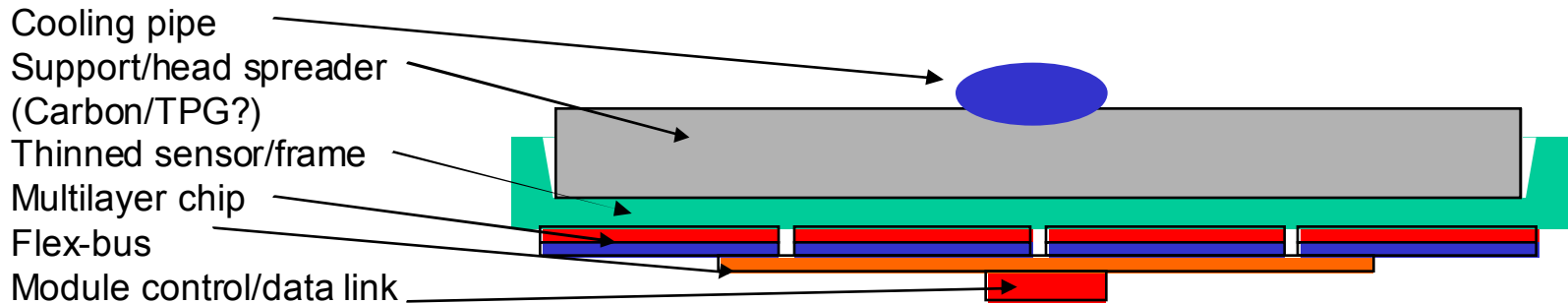


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# Conceptual Module Design of a SLHC pixel module

Work on conceptual module design:

use potential of 3D technology.  
reduce material: reduced thickness,  
higher integration -> less services.



## Cooling of ASIC & Sensor:

~ 100  $\mu\text{m}$  Si  $\Delta T < 10\text{mK}$  for  $p=50\mu\text{W}/\text{pixel}$  ( $50 \times 200 \mu\text{m}^2$ ).

## Material ( $X_0$ ):

Sensor & ASICs: 0.12 – 0.26 %

Carbon/TPG (.5 mm): 0.2 %

Flex, MCC,.. ~0.1 %

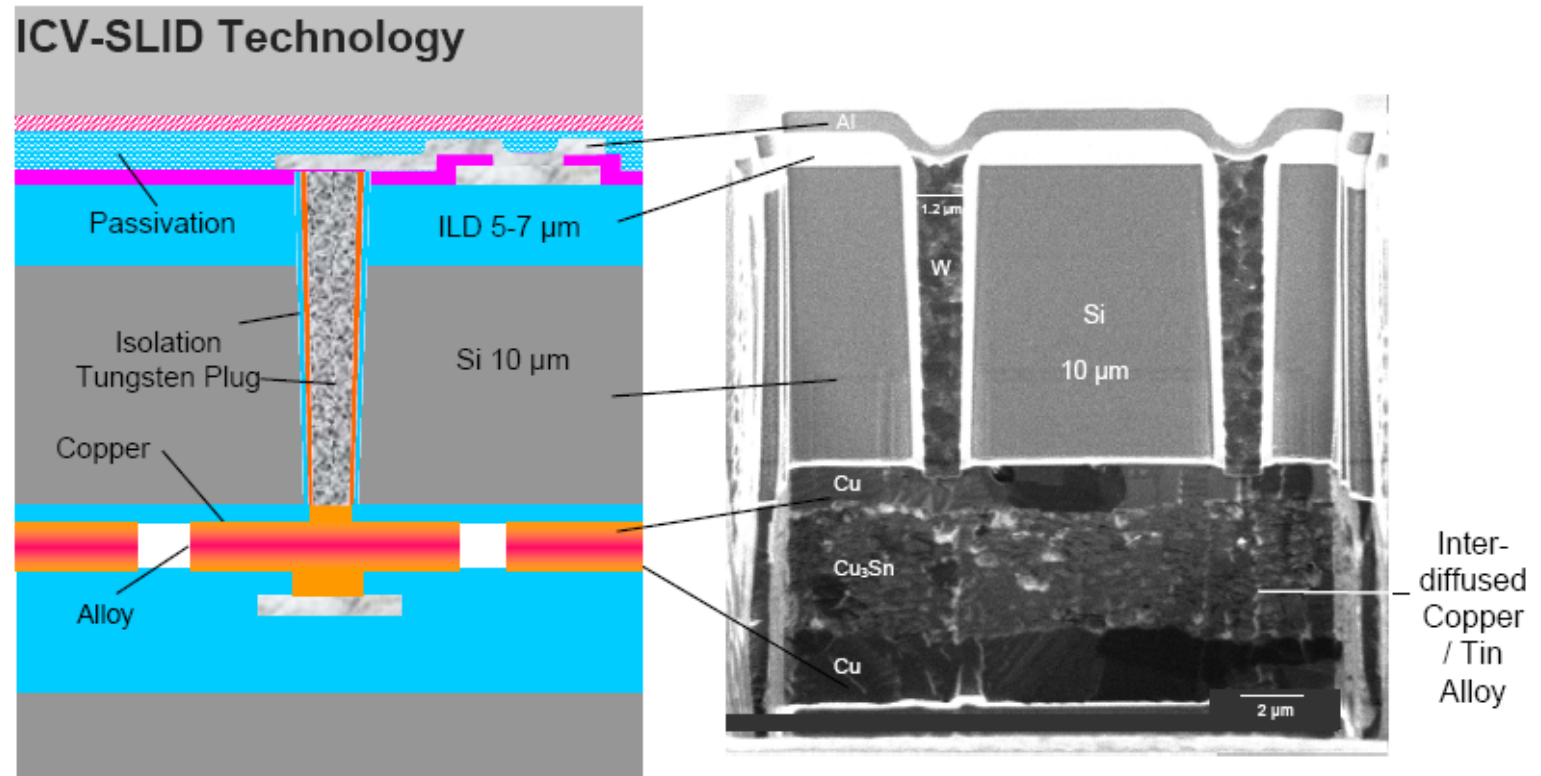
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0.42-0.56 % & less support & services



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# Through Silicon Vias



**ICV = Inter Chip Vias**

- Hole etching and chip thinning
- Via formation with W-plugs.
- Face to face or die up connections.
- 2.5 Ohm/per via (including SLID).
- No significant impact on chip performance (MOS transistors).

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18. 12. 2006

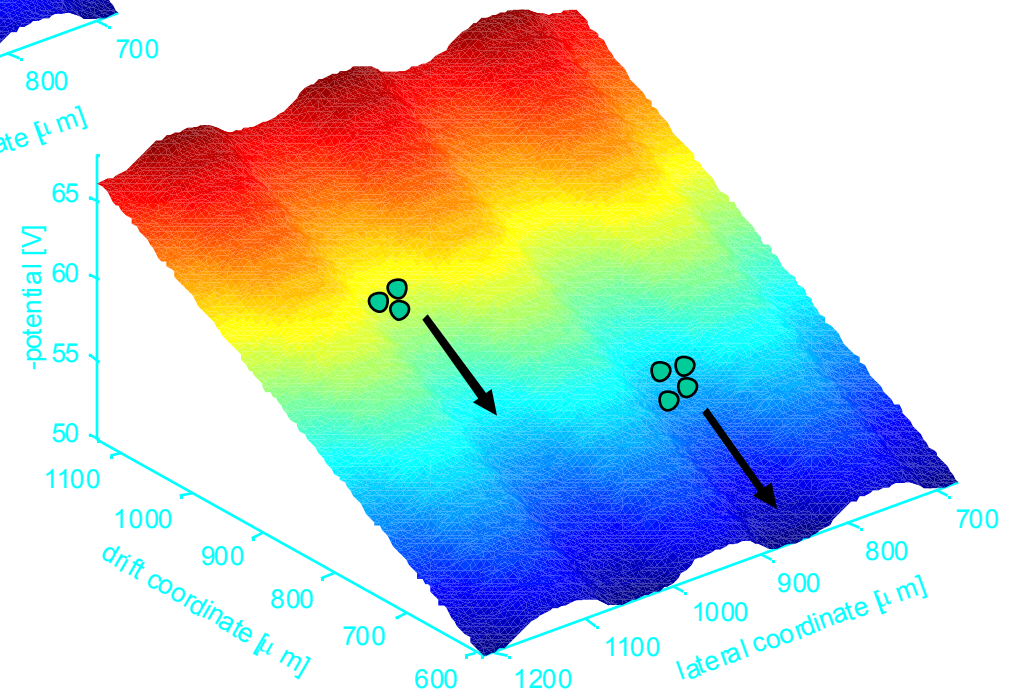
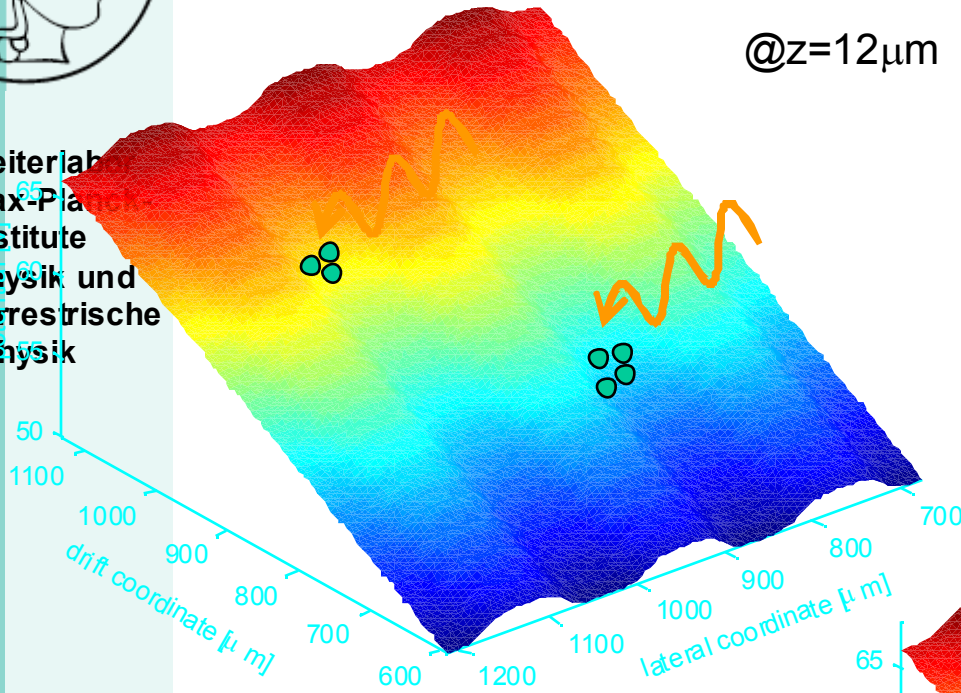
Fraunhofer **IZM**  
Institut  
Zuverlässigkeit und  
Mikrointegration



# Linear – Silicon -Drift Detector - simulation

@z=12μm

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The X-ray position along the drift is  
obtained from the electrons' drift time

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$T_{\text{drift}} \sim 1000 \text{ ns} / 12.8 \text{ mm}$

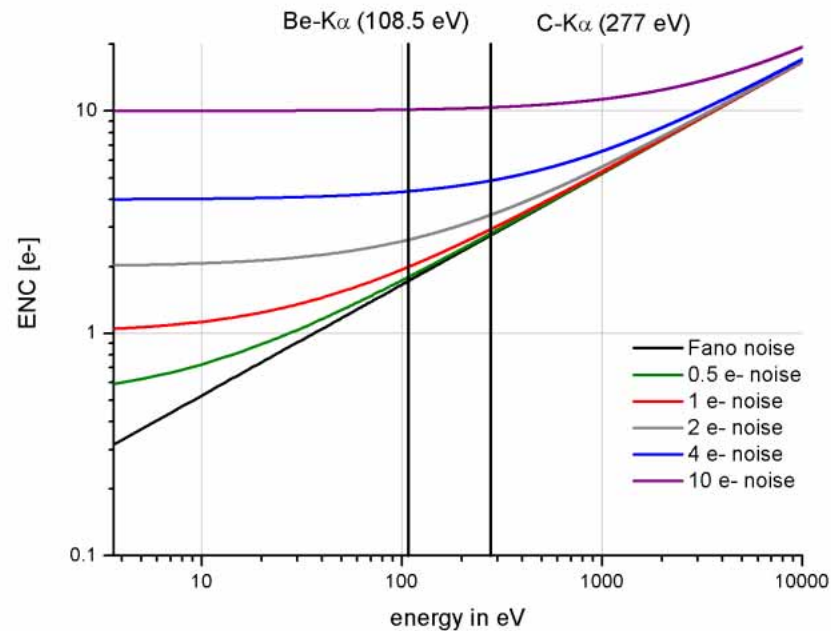




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## What are possible applications?

- » Ultra low noise detector for x-rays
  - low energy x-rays
  - strong red-shifted x-ray sources



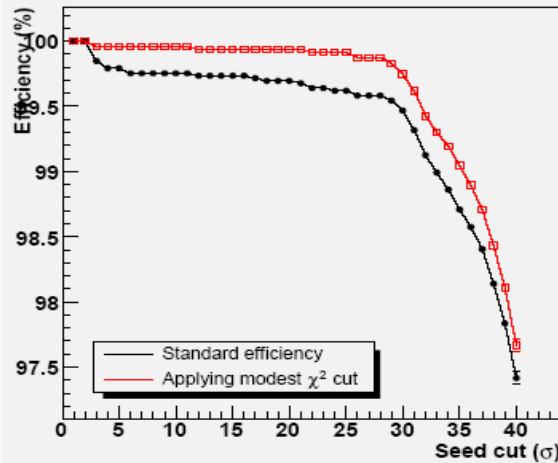
$$ENC_{\text{tot}} = \text{sqrt}(ENC_{\text{fano}}^2 + ENC_{\text{el.noise}}^2)$$



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# Efficiency & Position resolution

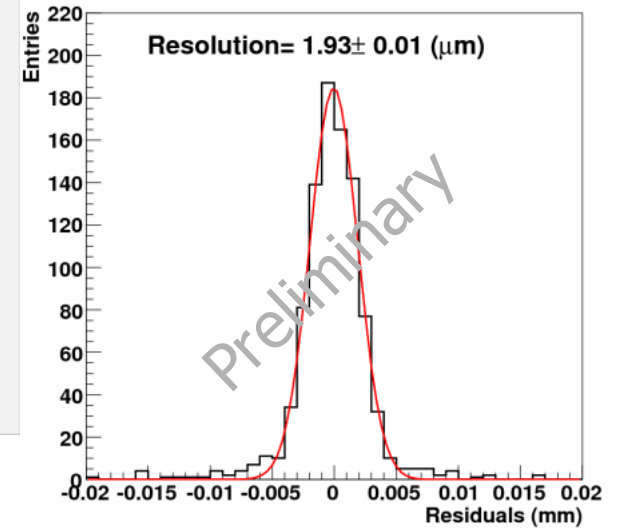
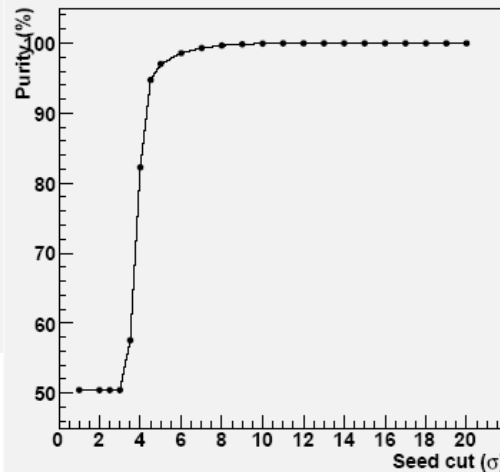
Efficiency vs seed cut



$$\text{Efficiency} = \frac{\text{Number of tracks with cluster}}{\text{Total number of tracks}}$$

$$\text{Purity} = \frac{\text{Number of clusters with tracks}}{\text{Total number of clusters}}$$

Purity vs seed cut



(Jaap Velthuis)

For 5  $\sigma$  seed cut

- Efficiency  $\approx$  99.96%
- Purity  $\approx$  99.6 %

First preliminary result from CERN test beam,

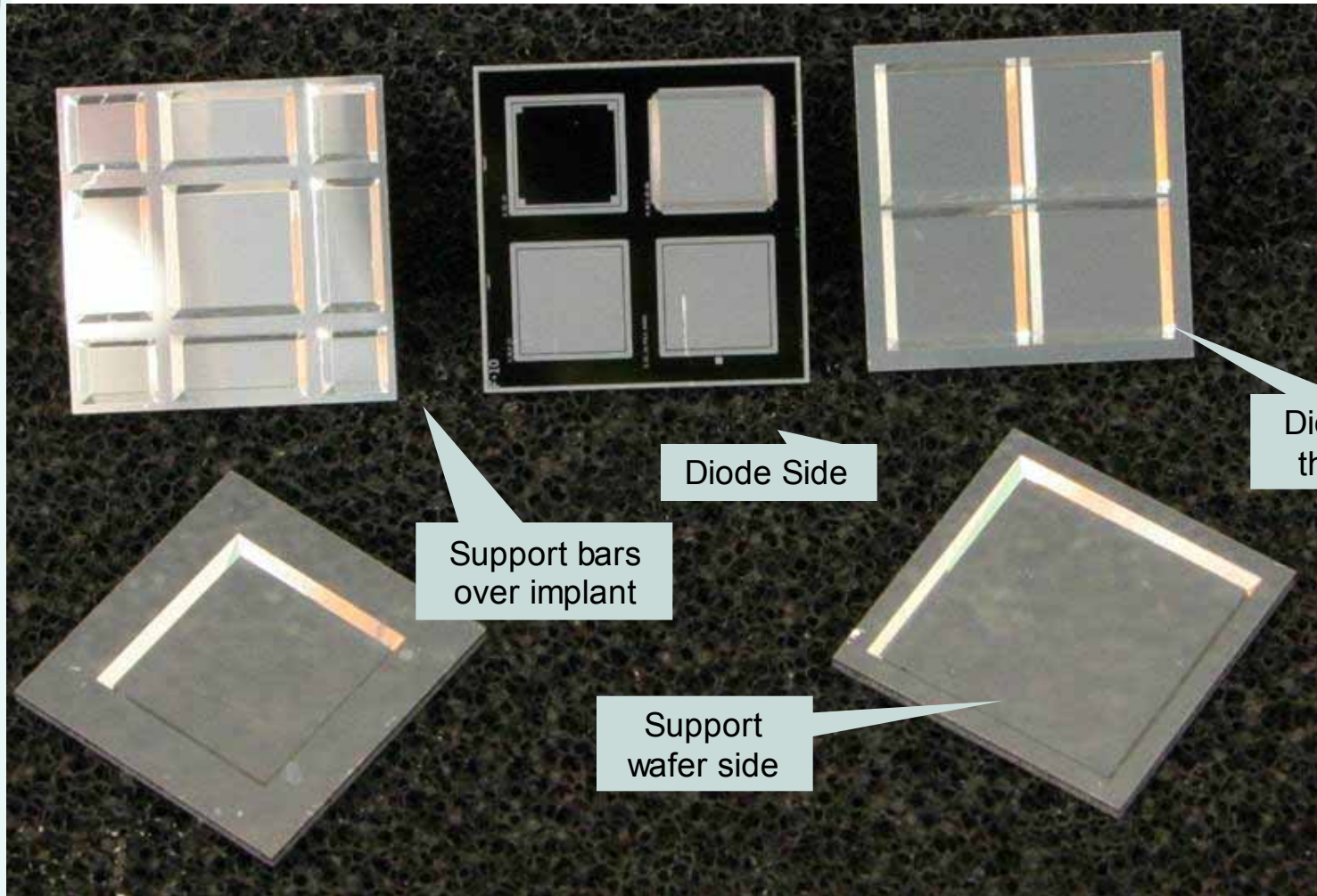
129 GeV  $\pi$ , 33x23.75  $\mu\text{m}^2$  pixels

**position resolution  $\approx$  2  $\mu\text{m}$**



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## PiN Diodes with Different Support Sides



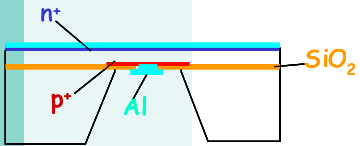
1cm



# The 3<sup>rd</sup> round - SOI Wafers in preparation...

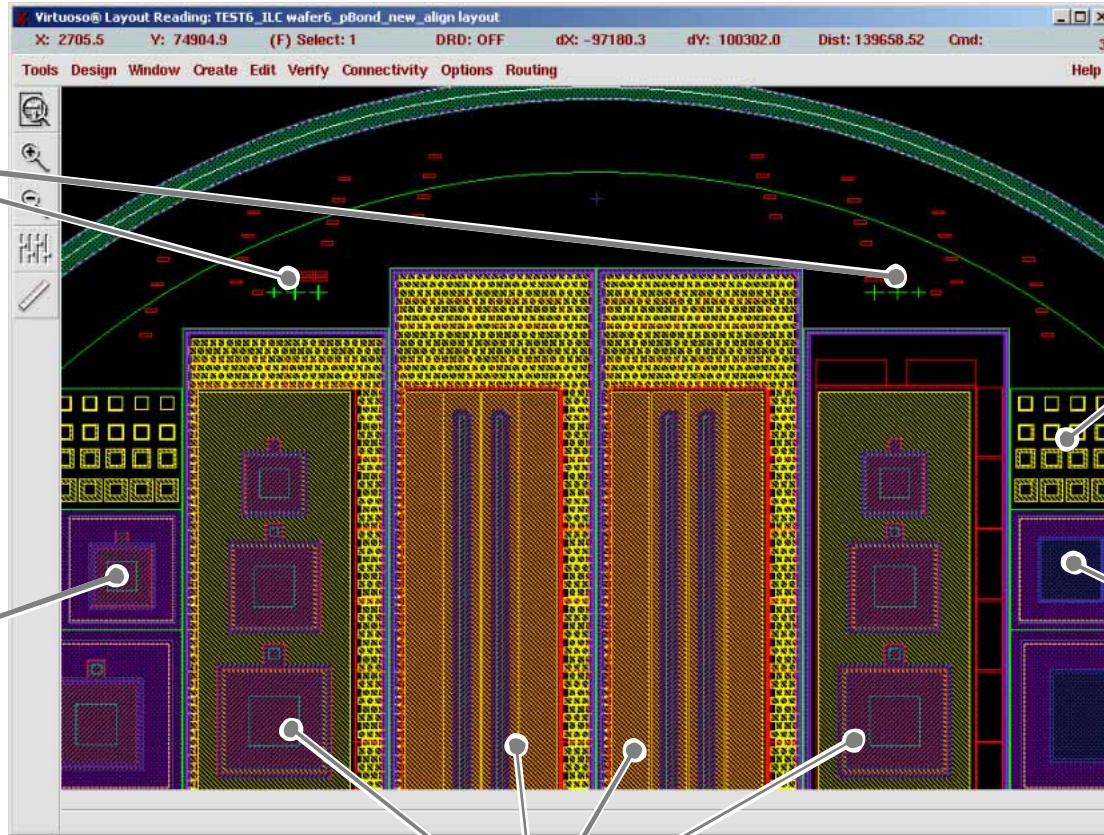
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Physik  
*Implant like DEPFET config.*



unstructured n+ on top  
structured p+ in bond region

Diodes with  
various areas



Some test  
structures

MOS-C with  
various areas

4 "full size" 1<sup>st</sup> layer ladders  
100x13 mm<sup>2</sup>, 1 and 3 mm frame  
along the long side